

Magnetoresistive sensors: steps towards the perfect sensor

Susana Cardoso de Freitas

Developing path of magnetic sensing technology

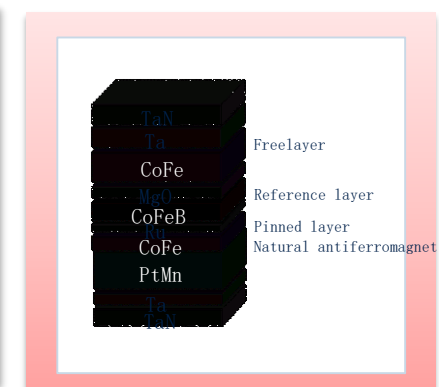
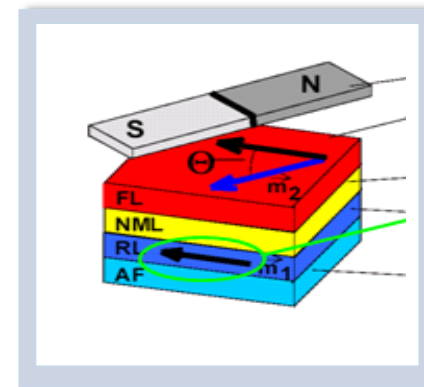
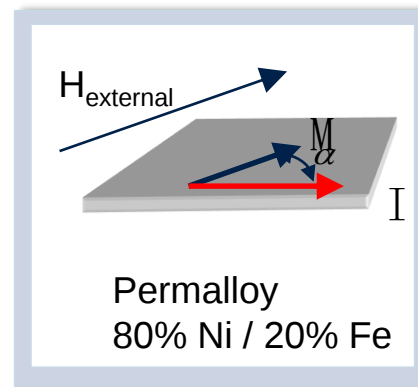
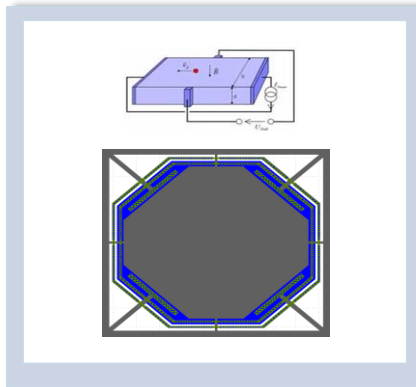
Hall Sensor → AMR → GMR → TMR
Spinvalve

Hall effect
 $0.2 \sim 0.8 \text{ mV/V/Gs}$

AMR effect
 $0.1 \sim 0.3 \text{ mV/V/Gs}$

GMR effect
 $0.2 \sim 1 \text{ mV/V/Gs}$

TMR effect
 $2 \sim 10 \text{ mV/V/Gs}$



Hard Disks

1986 → 1996 → 2004 →

SENSORS

Hall

AMR

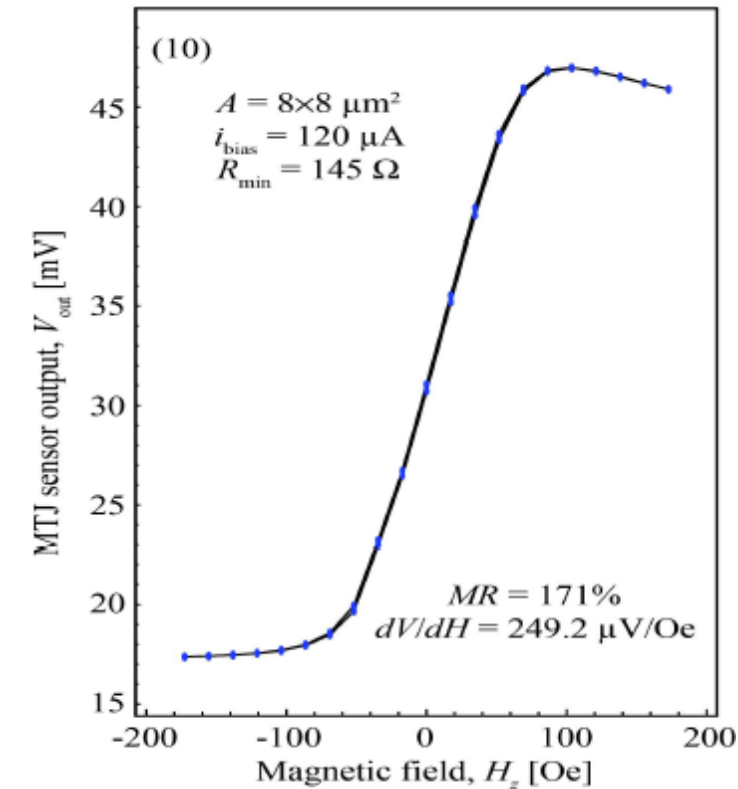
GMR

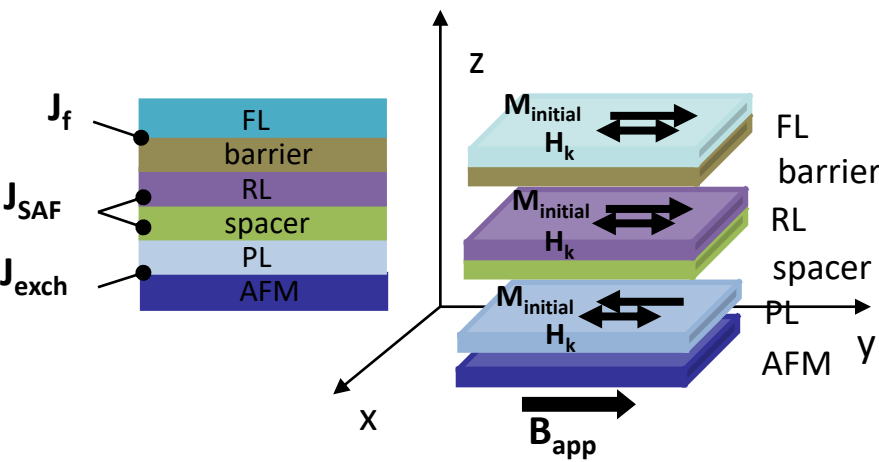
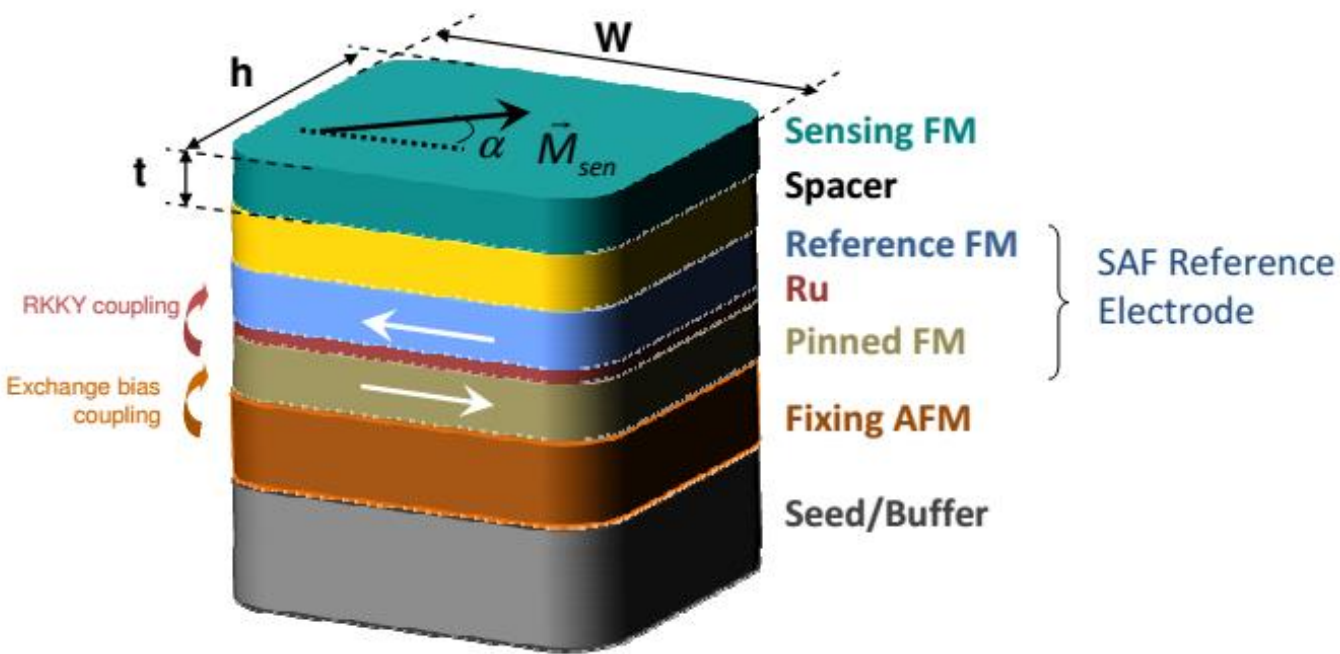
TMR

The perfect magnetoresistive sensor

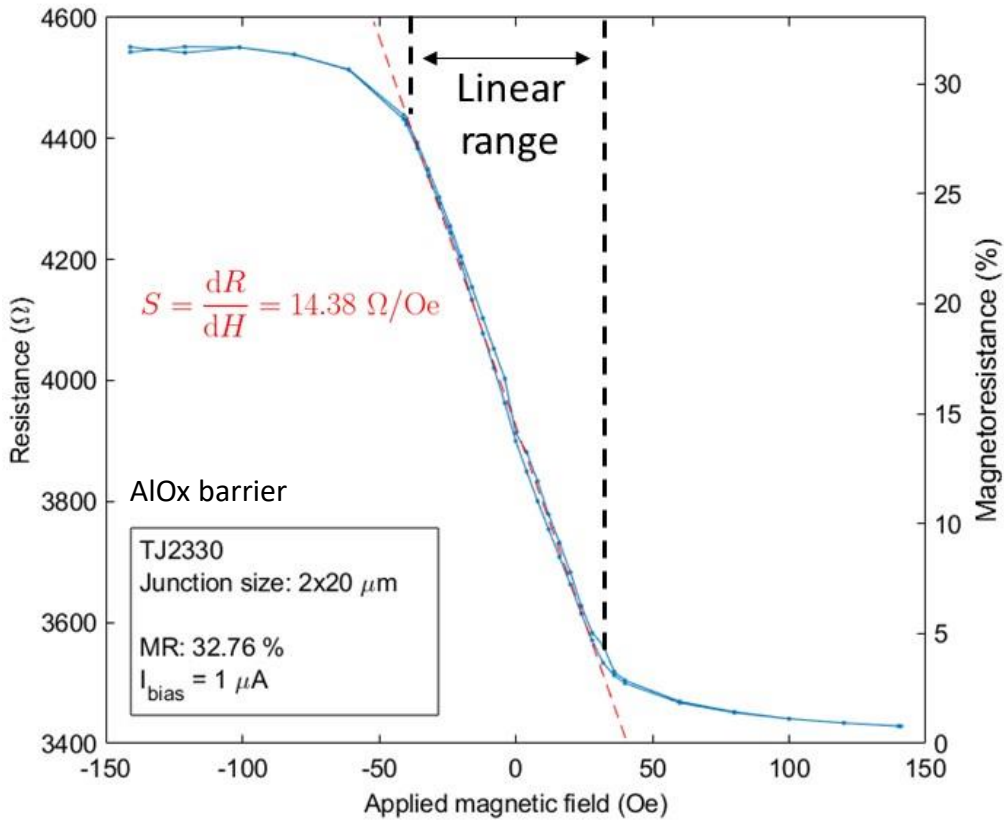
IEEE Trans Magn. 53 (4), 5300204 (2017)

- large output voltage: mV
- low field detection: pT
- tunable for large field detection: 80 mT
- low noise
- low hysteresis 0 mT
- linearity: < 1% non-linearity
- small footprint: 10 μm chip size
- low cost: < 0.20 €/chip
- high thermal stability: >120°C in harsh e.m environment
- compatible with CMOS modules
- compatible with large scale microfabrication
- compatible with flexible electronics

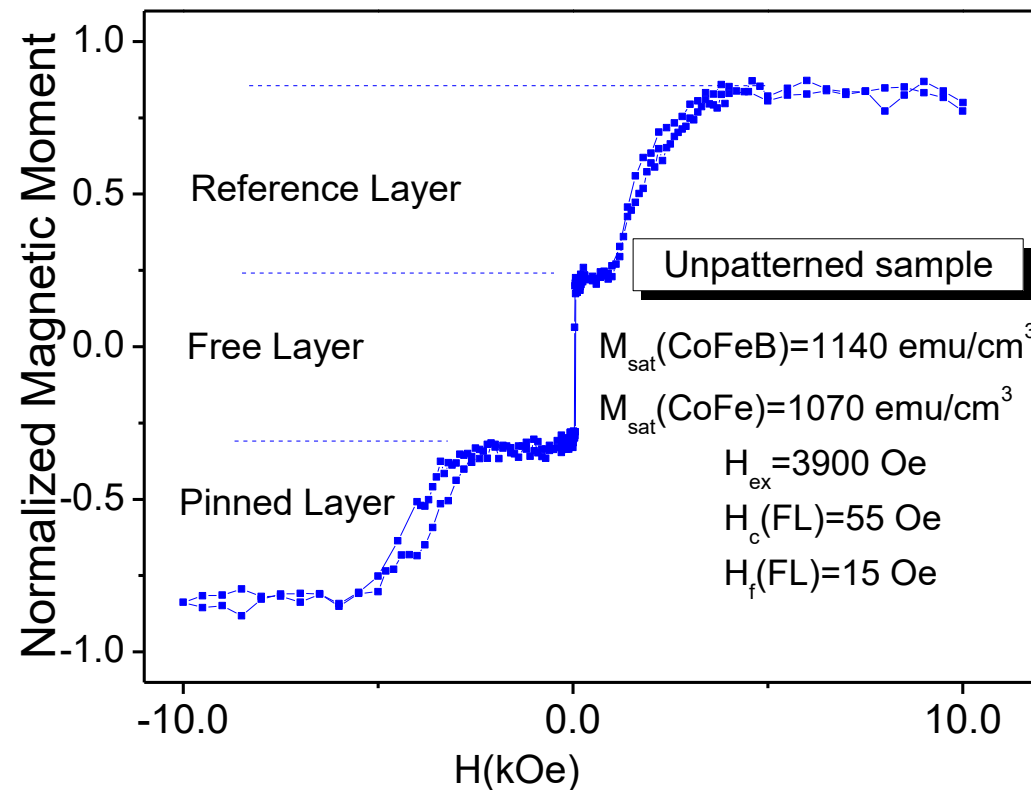
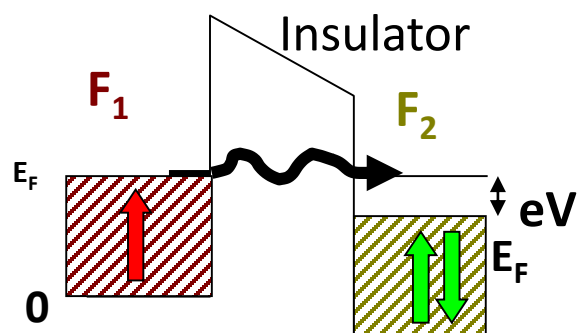
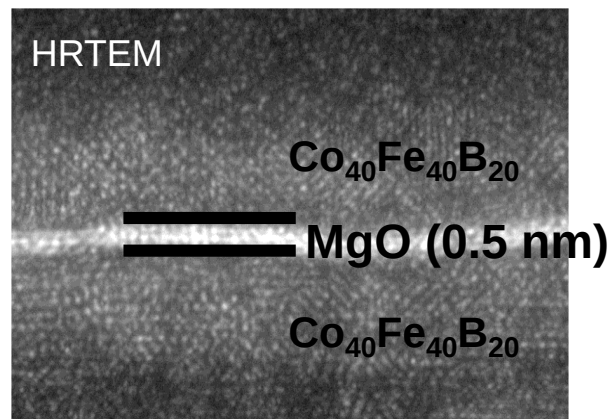




TMR sensor with AlOx barrier (2001)



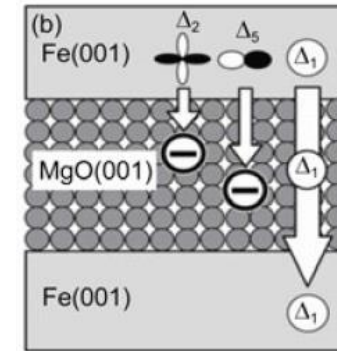
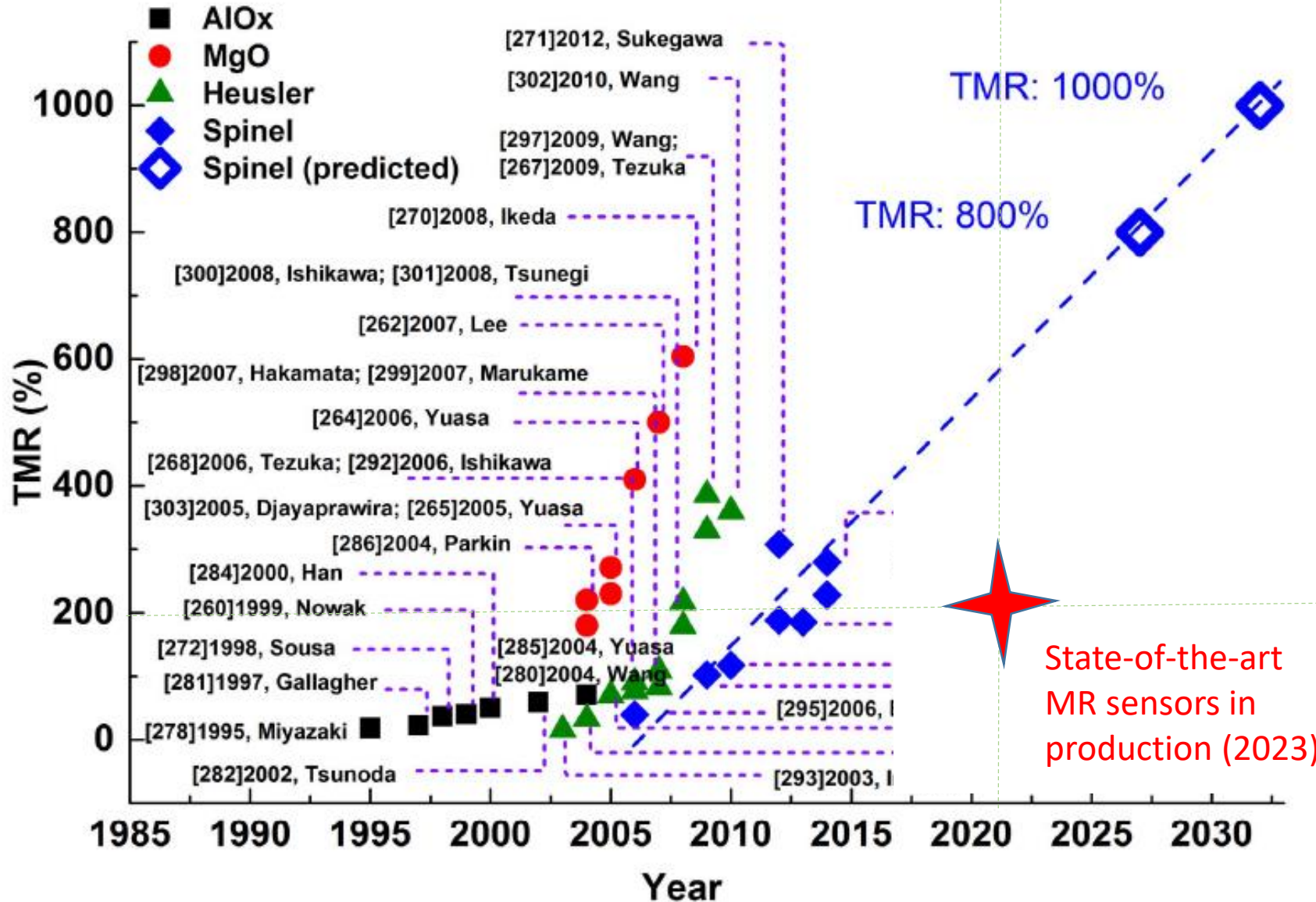
Magnetic tunnel junction - TMR



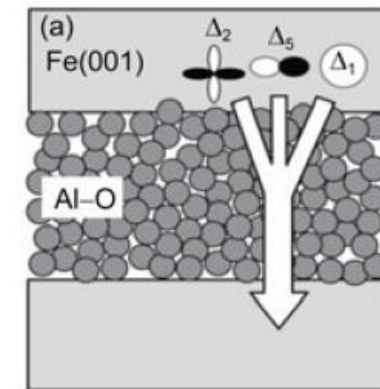
MIT, 1996
IBM, 1997
INESC, 1997

Electrons will tunnel if apply voltage between electrodes
Spin is conserved upon tunneling

AlOx and MgO barriers

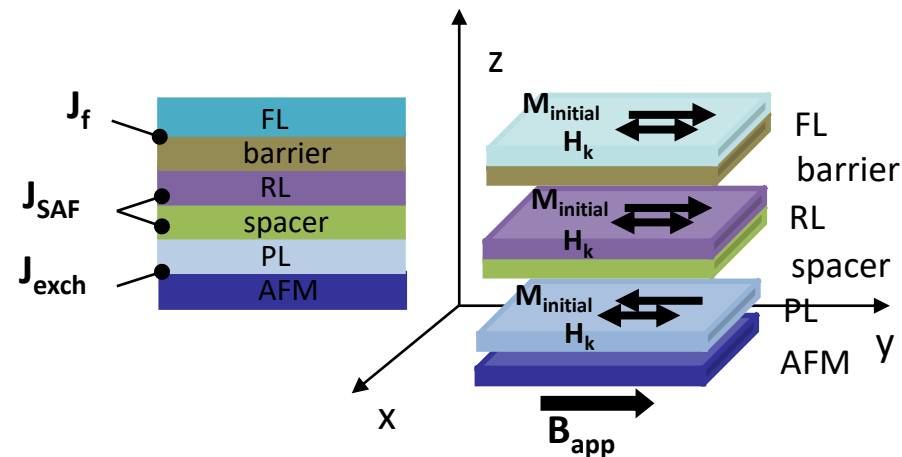
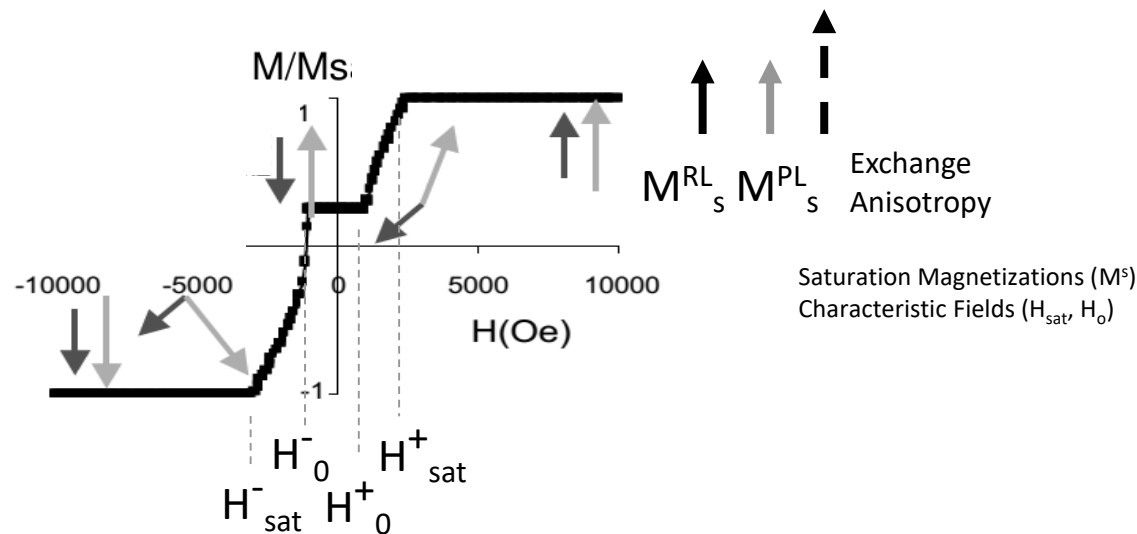


Crystalline barrier



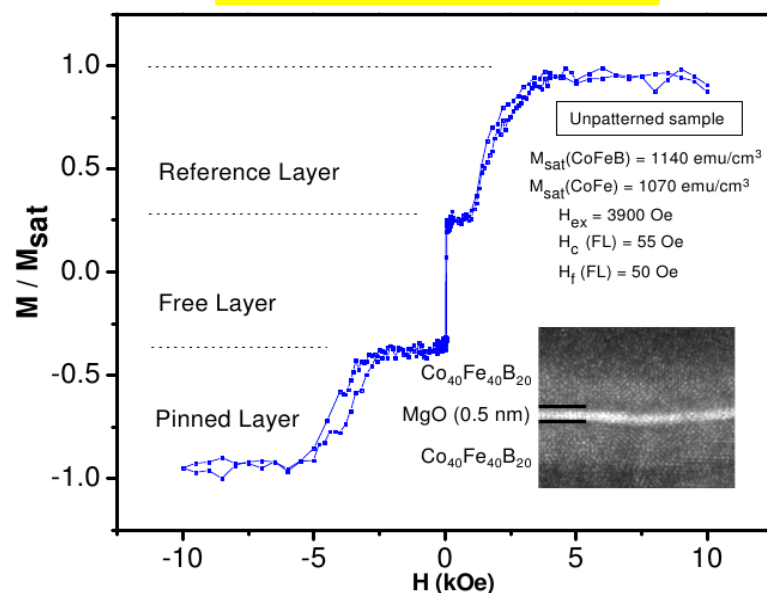
Amorphous barrier

Micromagnetic and Analytical Models



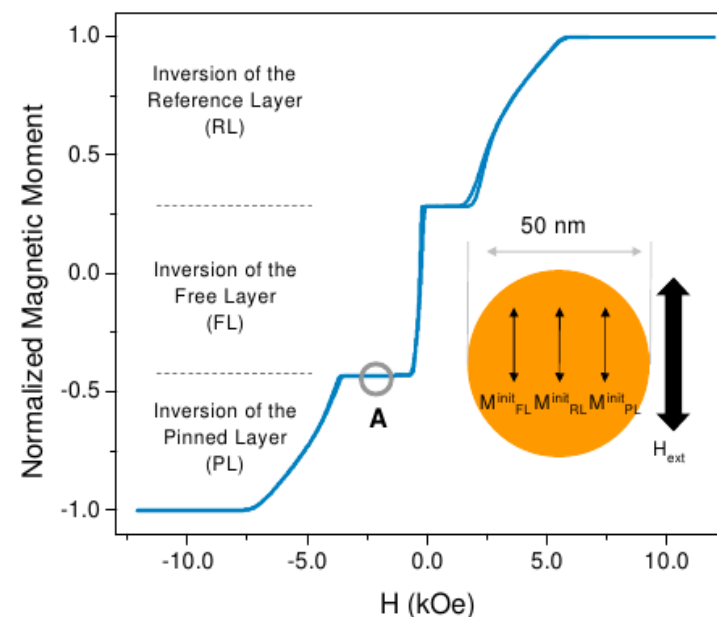
Nanotechnology 27, 045501 (2015)
Magnetolectronics, Elsevier, Ed.
Mark Jonhson, 2004

Experimental

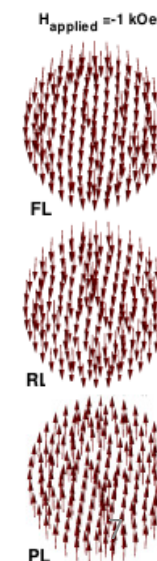


M_{sat}
 J_{exch}
 J_{SAF}
 J_f

Simulation

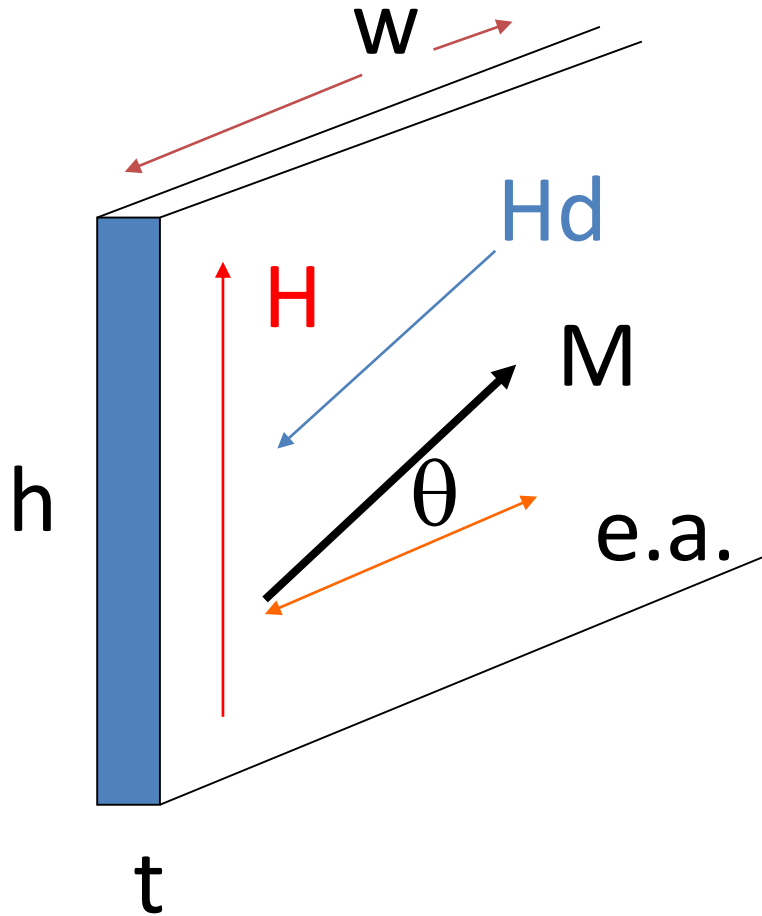


Micromagnetic distributions at A



Magnetic Energy of a semi-infinite thin film ($w \gg h, t$)

$$E/V = -\mu_0 \mathbf{H} \cdot \mathbf{M} + K \sin^2 \theta - \frac{1}{2} \mu_0 \mathbf{H}_d \cdot \mathbf{M}$$



Theory Magnetic Recording, N.Bertram

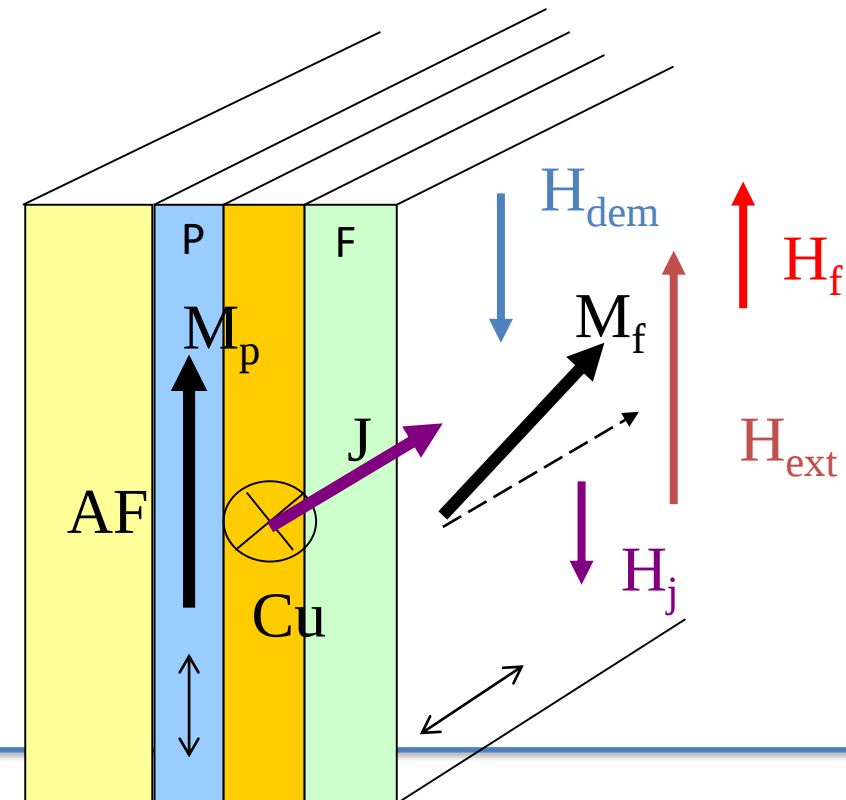
B.D.Cullity(1972) Introduction to Magnetic Materials

1- C.Tsang, et.al, IEEE Trans.Magn., 30, 3801 (1994).

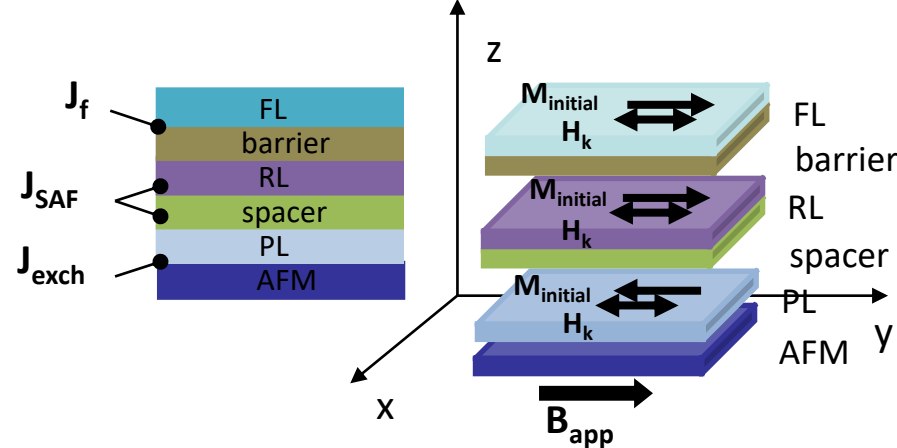
2- B.Dieny, et.al Phys.Rev.B, 43, 1297(1991).

3- D.E.Heim, et.al , IEEE Trans.Magn., 30, 316 (1994);

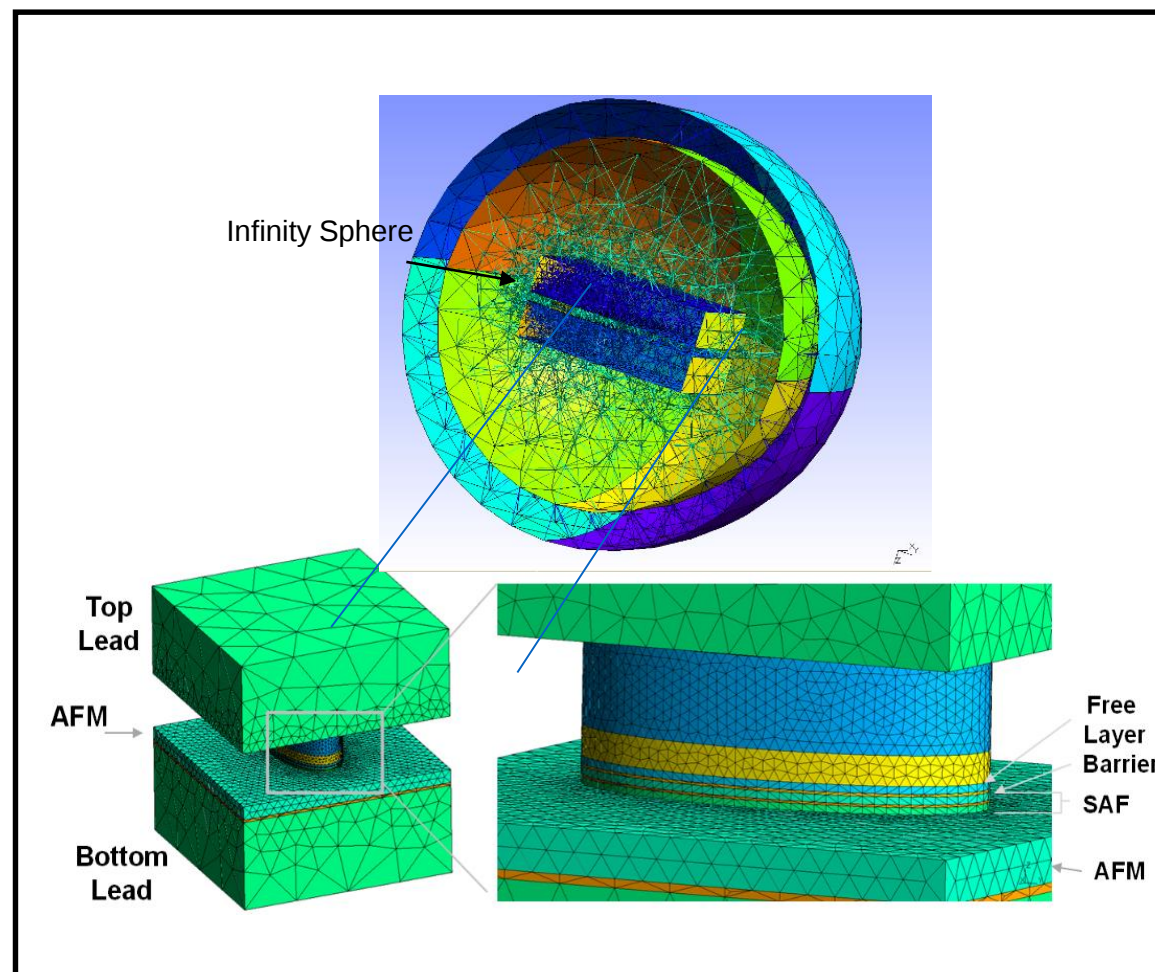
4- P.P.Freitas, et.al , Appl.Phys.Lett., 65, 493 (1994);



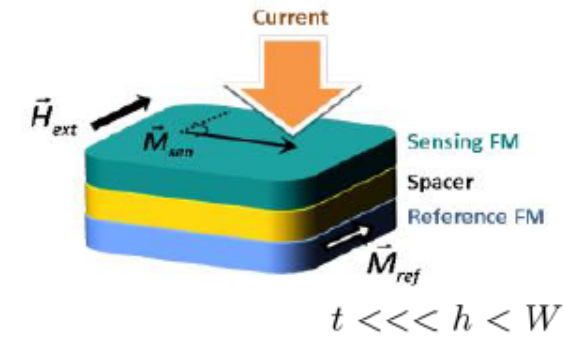
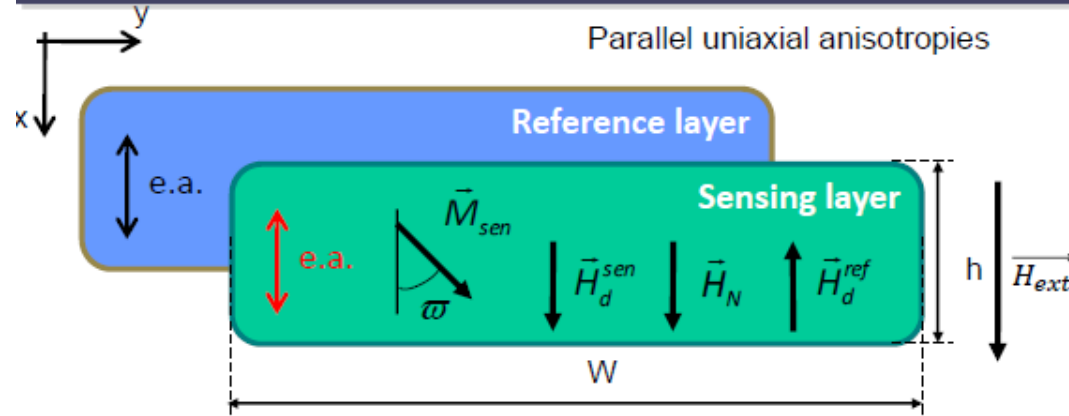
Modelling - micromagnetics



Magnetic volumic properties		
for all ferromagnetic volumes		
Saturation flux densities $\mu_0 M_s$	T	Initial M versor
Uniaxial anisotropy flux density H_k	T	Anisotropy versor
for all micromagnetic volumes		
Surface Energy Coupling constants (erg/cm ²)		
Allmicromagnetic surfaces		
Exchange coupling between PL and AFM	J_{exch}	
Néel Ferromagnetix Coupling	J_f	
AntiFerromagnetic coupling trough spacer	J_{SAF}	



Macrospin Model for MR sensors



Energy minimization

When $H_{ap} < H_d^{ref} - H_N - |H_k - N_h M_s^{sen}|$

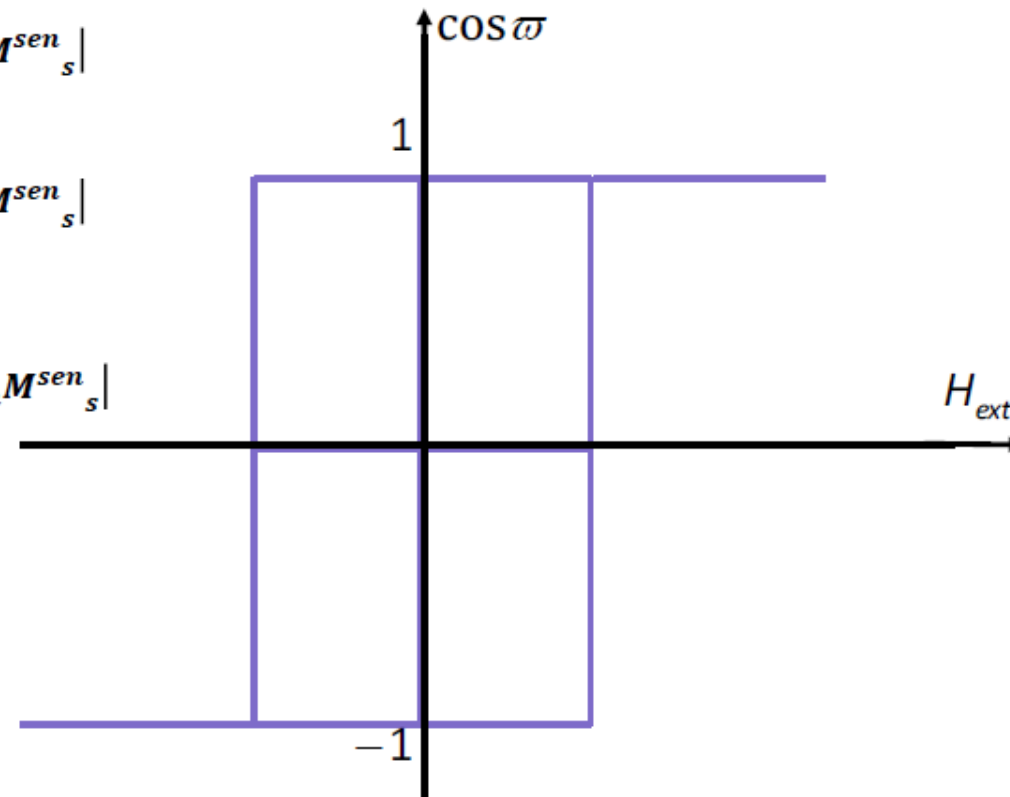
Minimum @ $\varpi = \pi$

When $H_{ap} > H_d^{ref} - H_N + |H_k - N_h M_s^{sen}|$

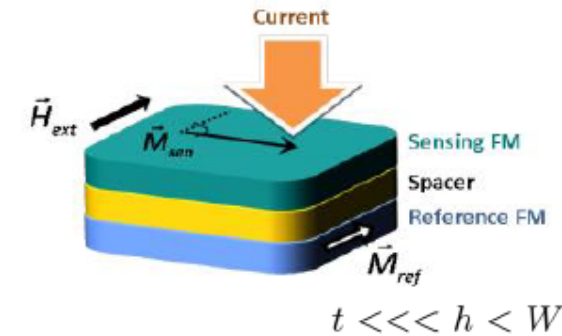
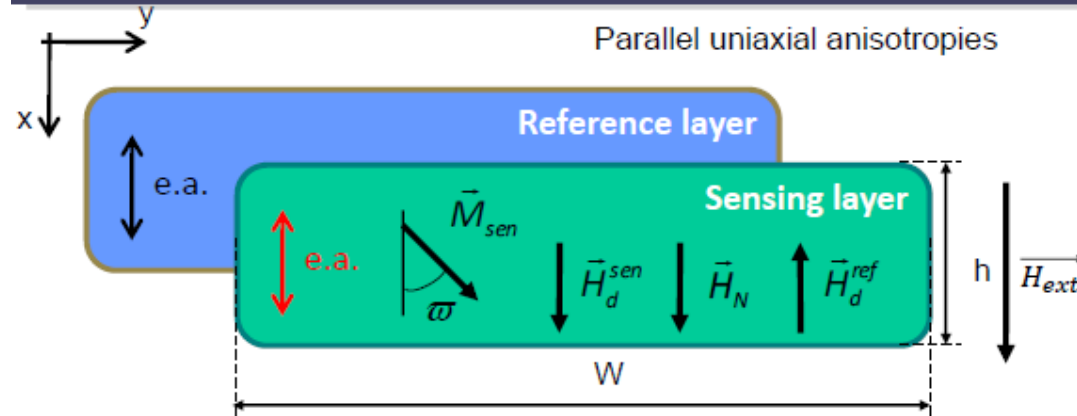
Minimum @ $\varpi = 0$

When $|H_{ap} - H_d^{ref} + H_N| < |H_k - N_h M_s^{sen}|$

2 situations can occur:
If $H_k > N_h M_s^{sen}$



Macrospin Model for MR sensors



Energy minimization

When $H_{ap} < H_d^{ref} - H_N - |H_k - N_h M_s^{sen}|$

Minimum @ $\varpi = \pi$

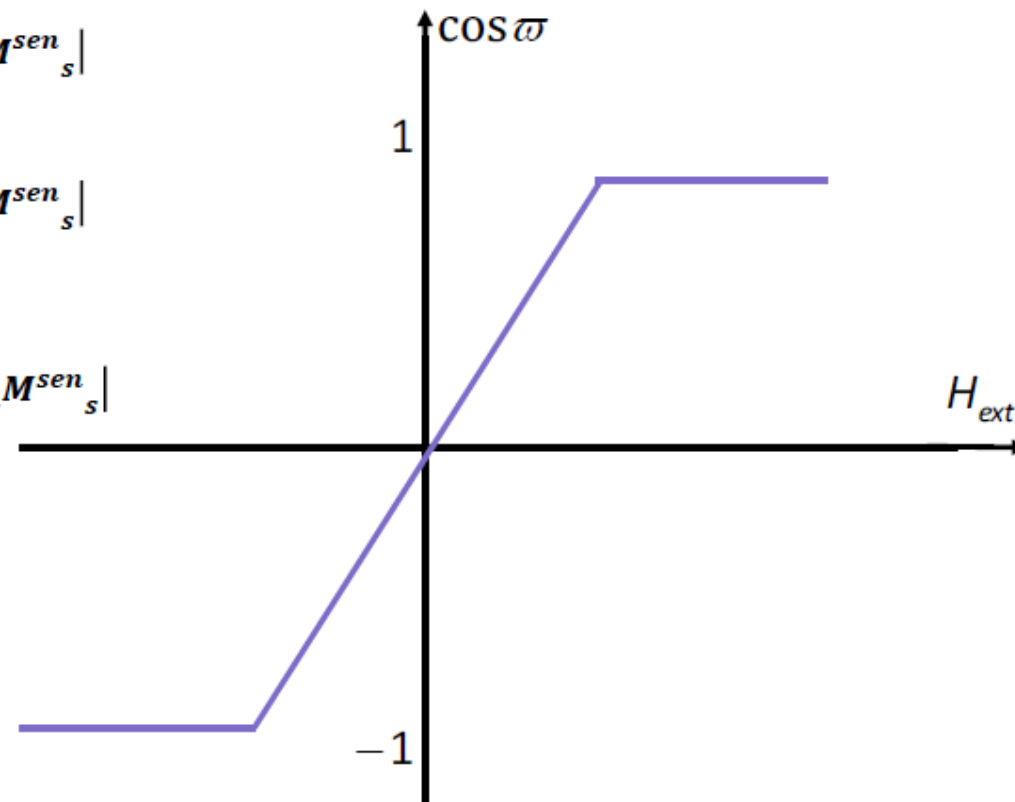
When $H_{ap} > H_d^{ref} - H_N + |H_k - N_h M_s^{sen}|$

Minimum @ $\varpi = 0$

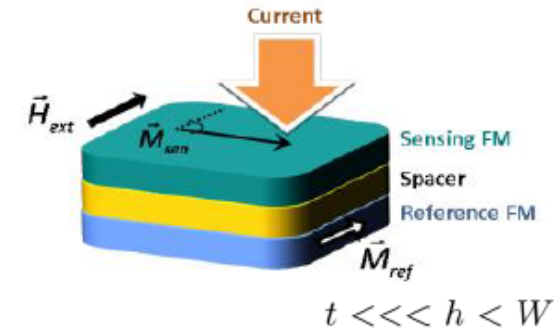
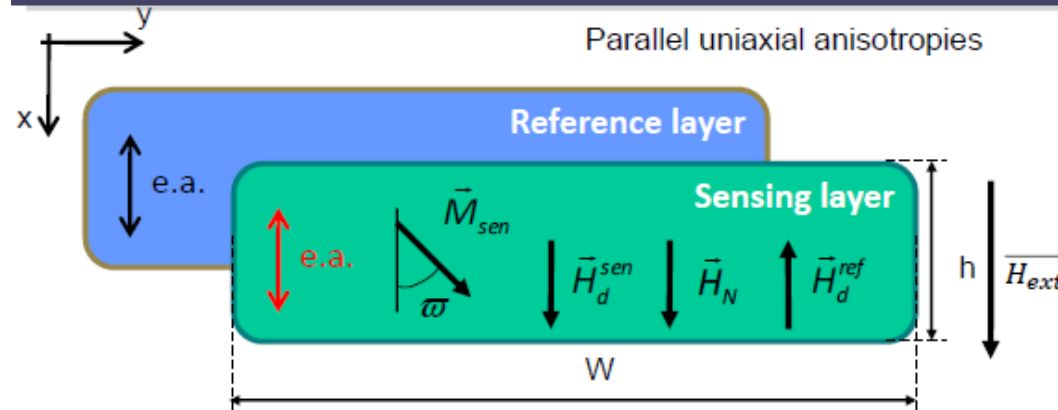
When $|H_{ap} - H_d^{ref} + H_N| < |H_k - N_h M_s^{sen}|$

2 situations can occur:

If $H_k < N_h M_s^{sen}$

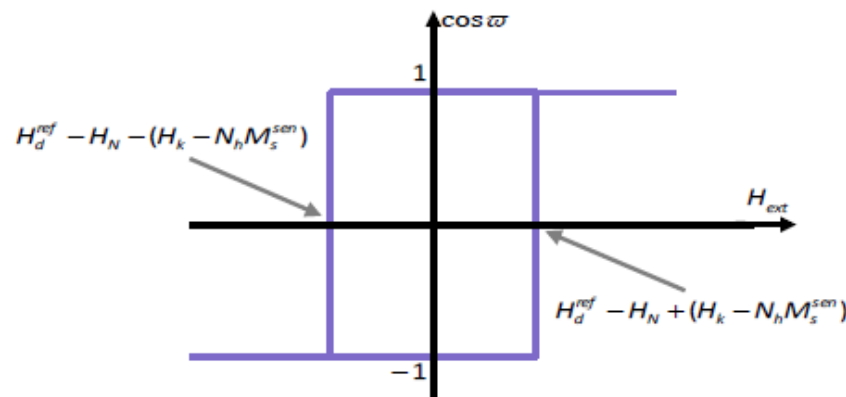


Macrospin Model for MR sensors



Final transfer curves

If $H_k > N_h M_s^{sen}$

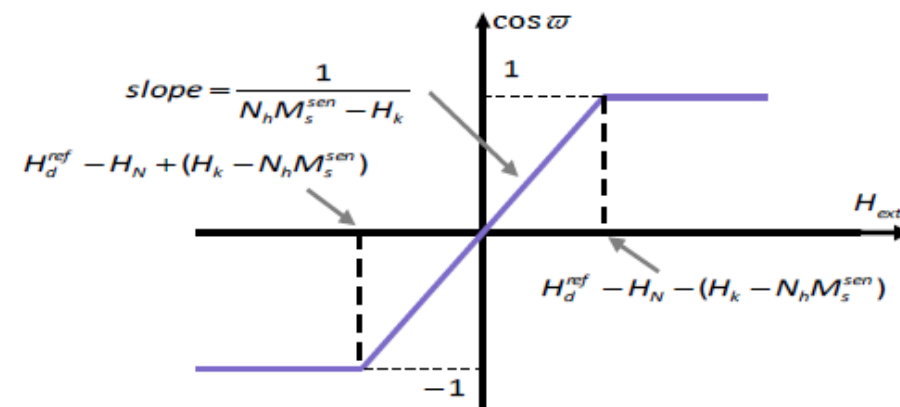


Memory applications:

Coercive field.

$$H_c = \frac{H_k - N_h M_s^{sen}}{2}$$

If $H_k < N_h M_s^{sen}$



Sensor applications:

Sensitivity $\propto \text{slope}$

Highest sensitivity when $H_k = N_h M_s^{sen}$

Linearization strategies for MgO-MTJ

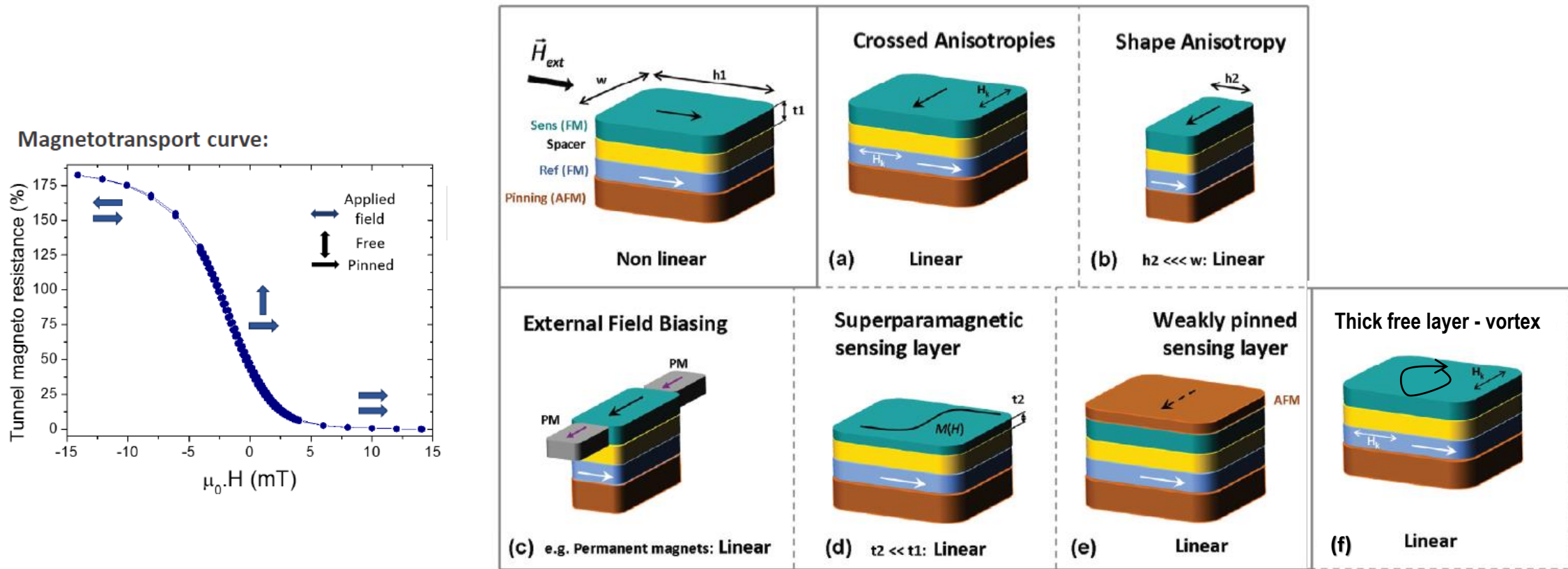
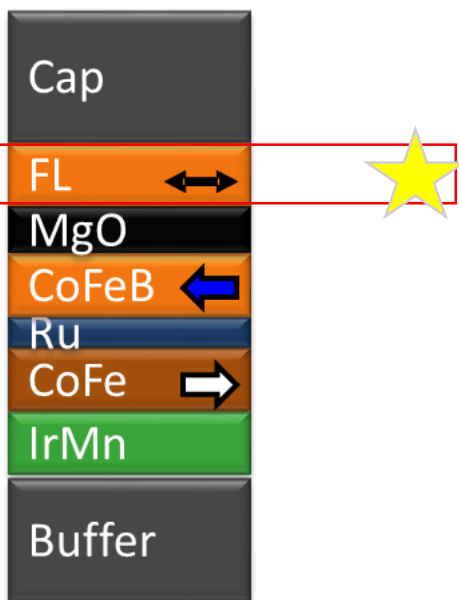
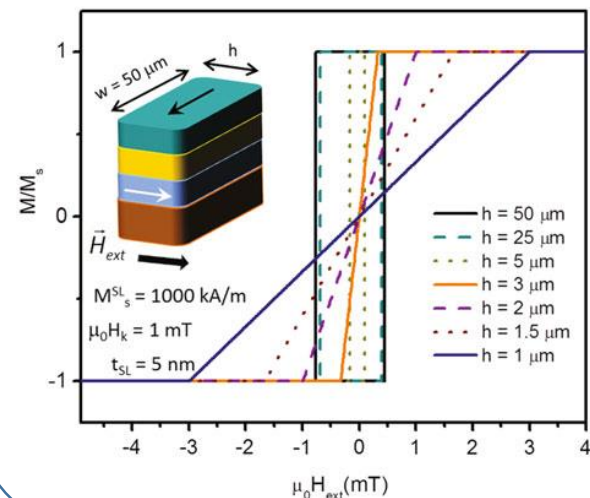


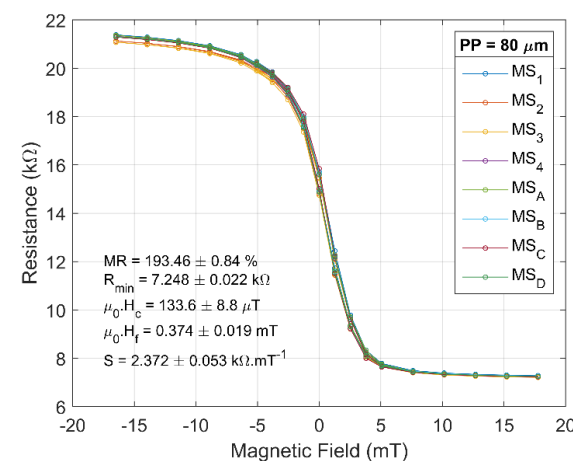
Fig. 12. Summary of linearization strategies for MR sensors.



Shape anisotropy



Weekly-pinned free layer



~ 1.8 – 6.0 nm (with linearization strategy)

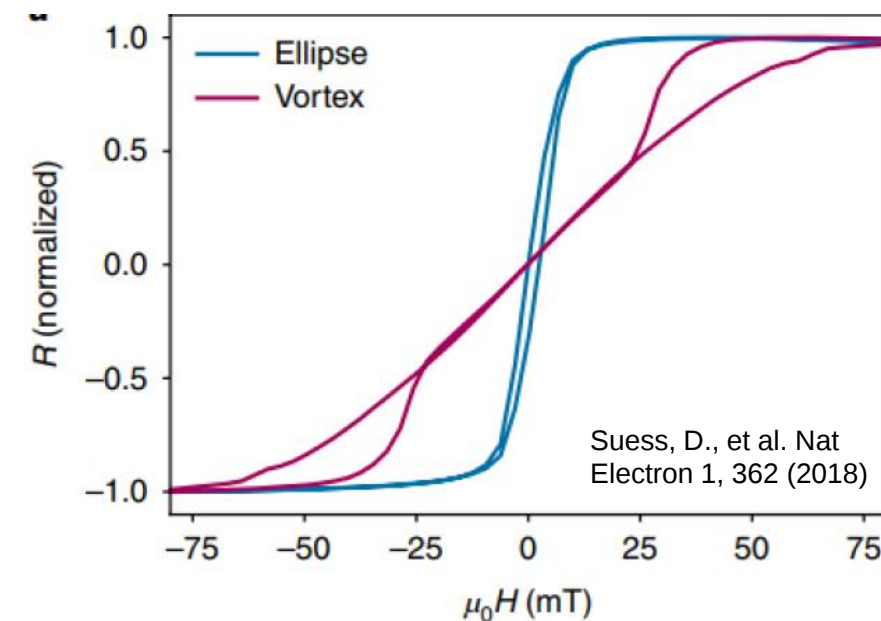
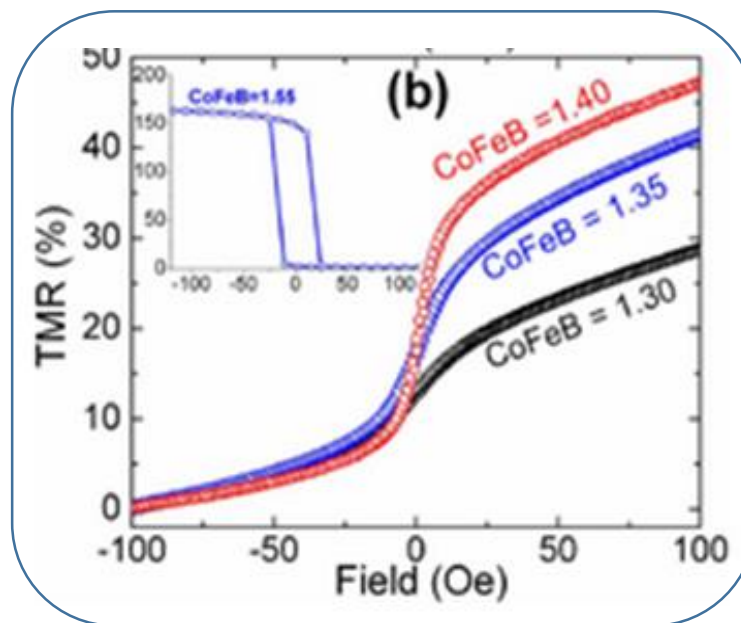
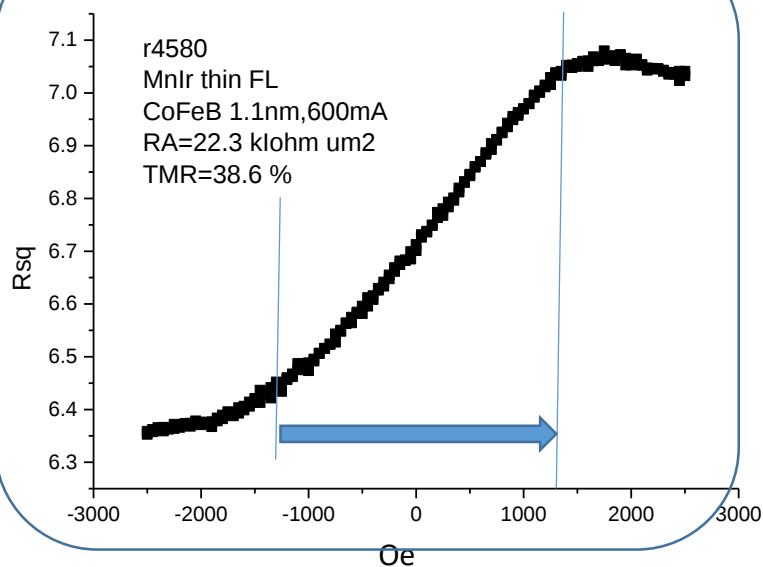
Free layer thickness

<< 1.3 nm

~ 1.3 - 1.5 nm

> 30 nm

> 200mT linear range



200mm backend GMR / TMR technology

TiWN

Ta 50 A

Ru 50 A

CoFeB(t)

MgO 13.5 A

CoFeB 30 A

Ru 9 A

CoFe 22 A

IrMn 200 A

Ta 30 A

Ru 180 A

Ta 50 A

substrate

F

R

P

B

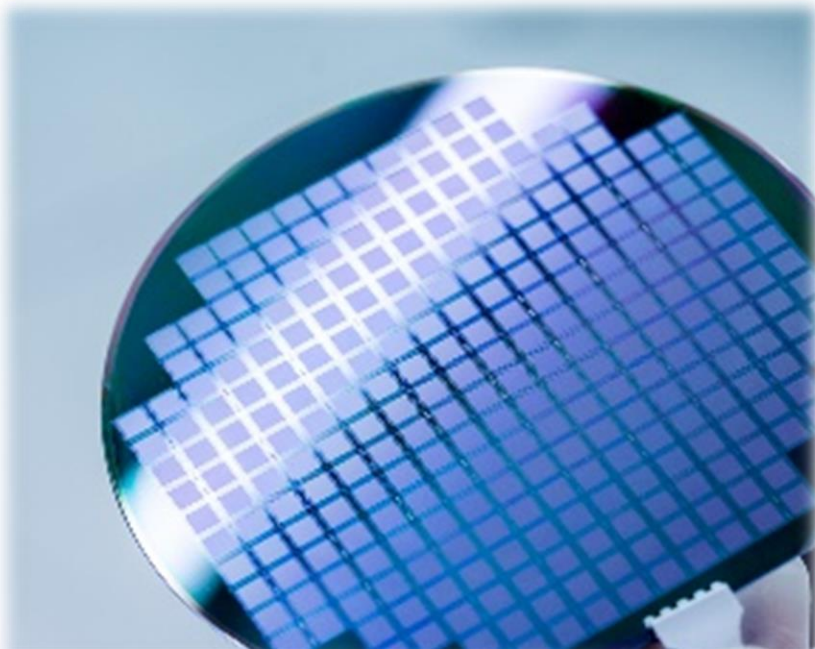
6 targets IBD (extra module
8 targets in PVD; 2019)

Dep pressure 2×10^{-5} Torr

Heated substrate

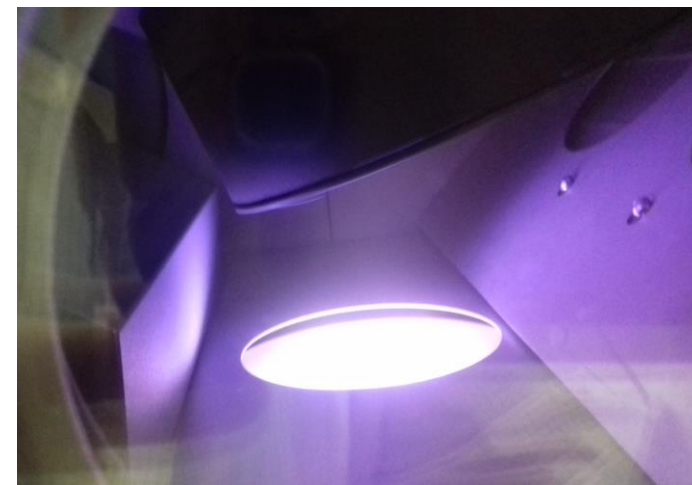
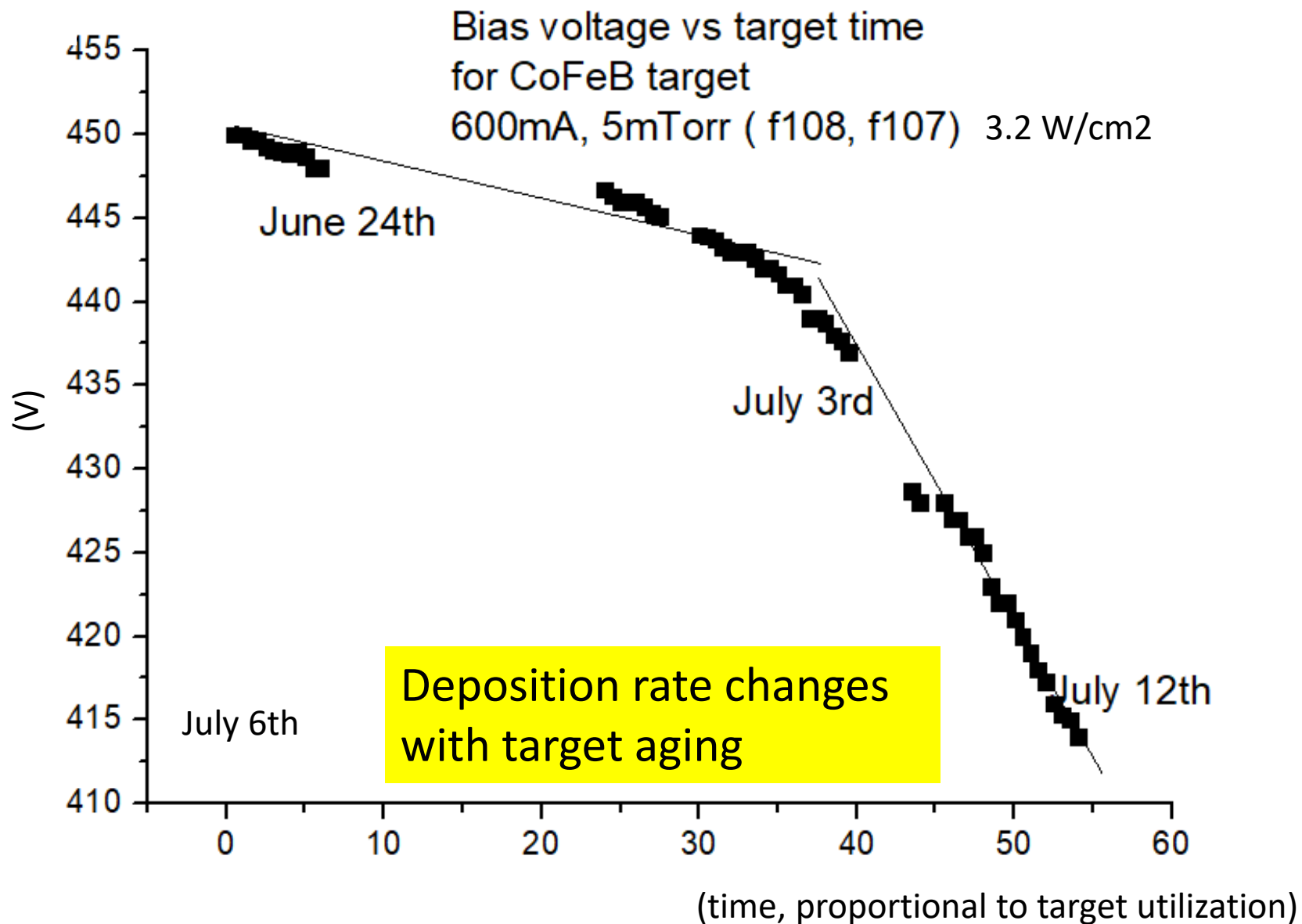
Assist gun,

Base Pressure 5×10^{-8} Torr



Nordiko
INNOVATION WITH RELIABILITY

Process control



CoFeB sputtering target (Ø100mm)

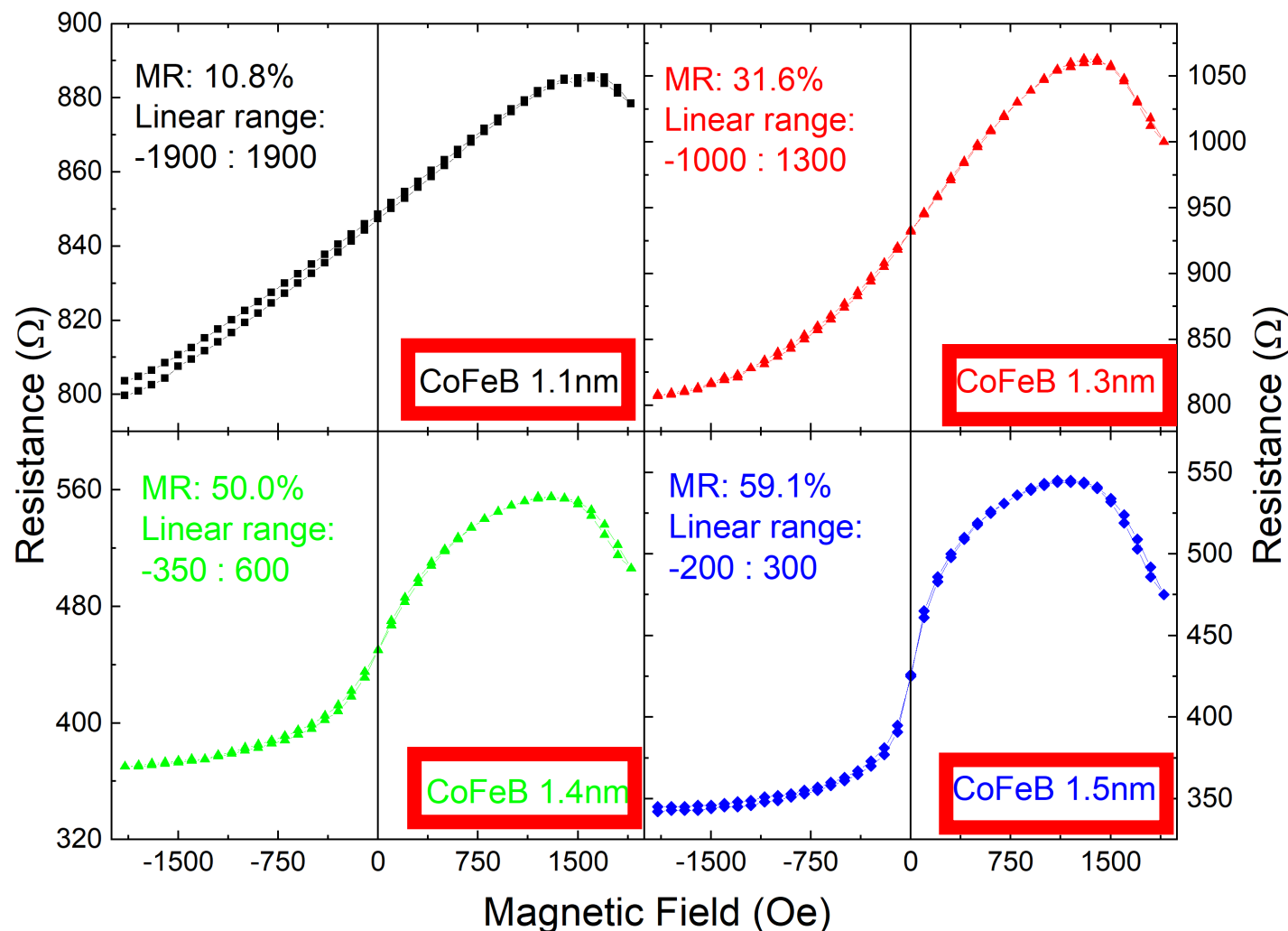
Process control: free layer thickness

Stack:

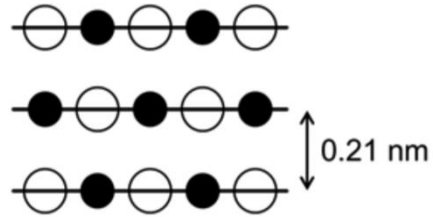
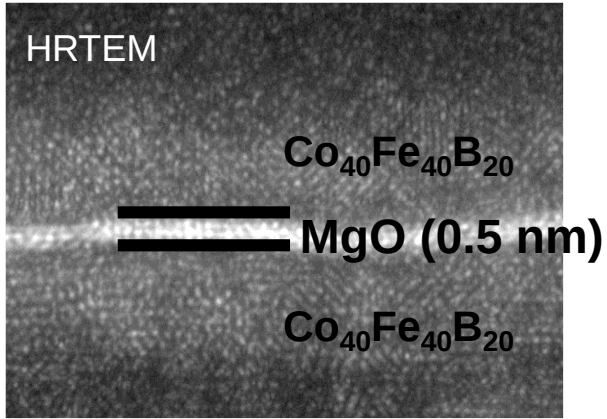
[Ta 5/Ru 10]_{x3}/Ta 5/Ru 5/MnIr 8/CoFe 2.2/Ru 0.65/CoFeB 2/MgO 1.6/**CoFeB t**/Ta 5/Ru 5/Ta 5/Ru 10

5μm squares

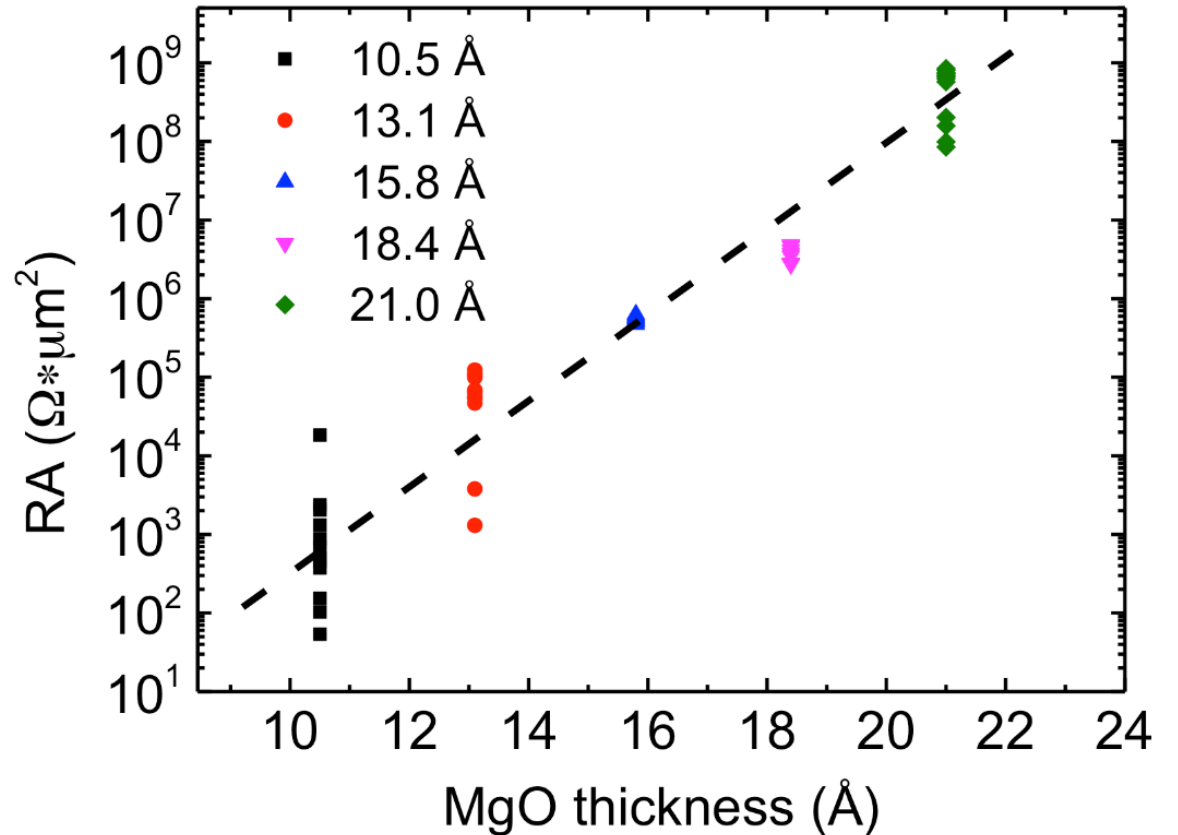
< 0.1 nm
thickness accuracy
needed



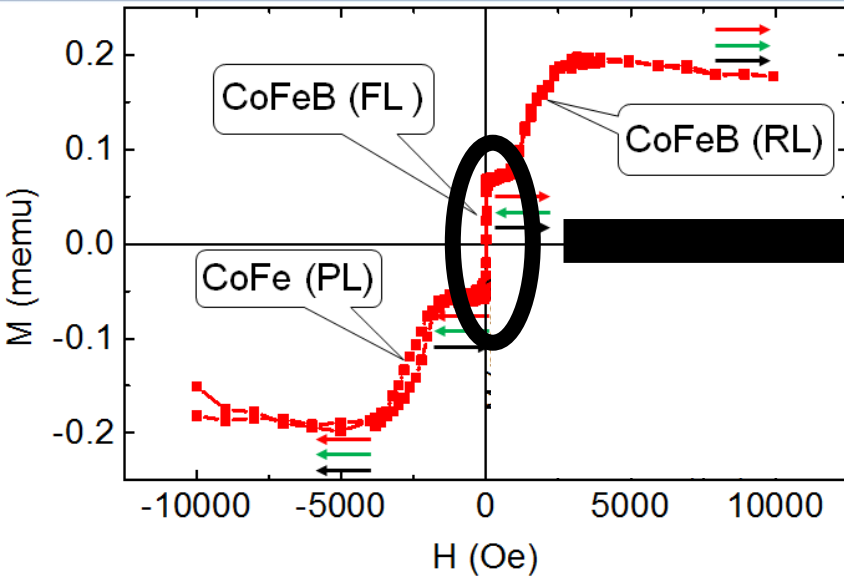
Process control: tunnel barrier thickness



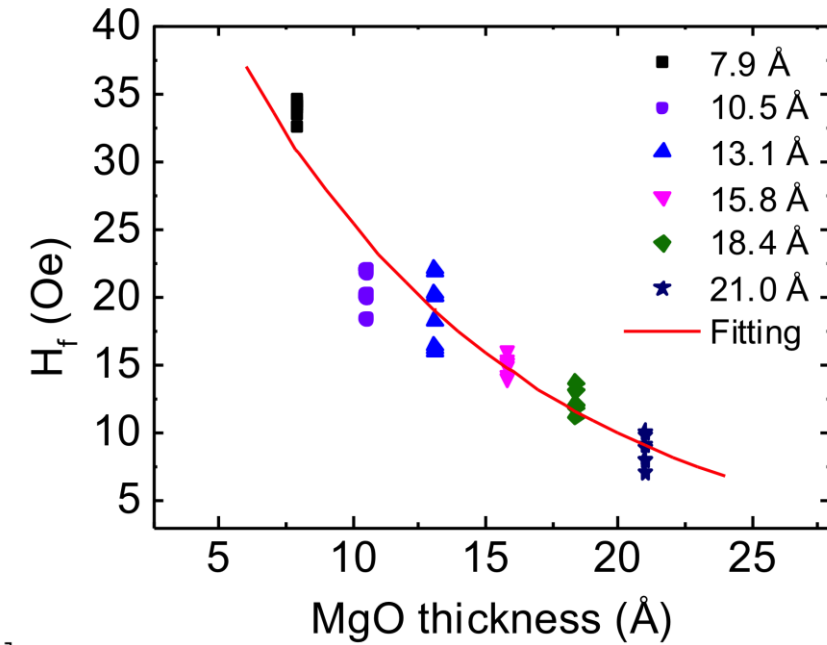
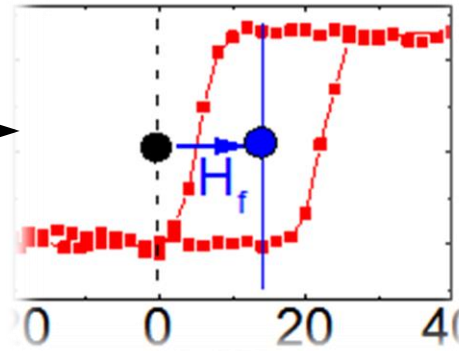
1 Å => 10x R



Interlayer magnetic coupling - Néel coupling

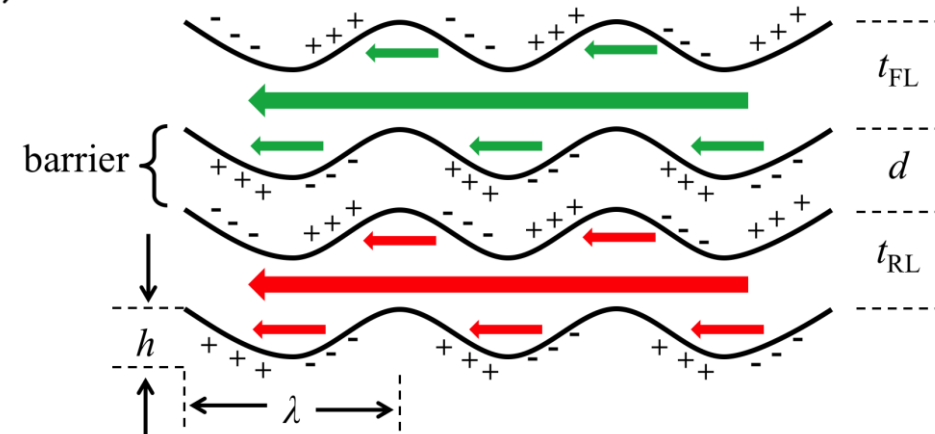
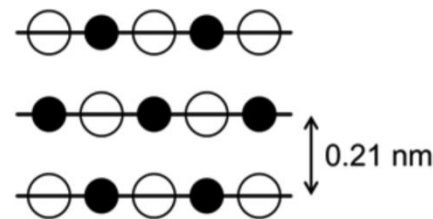


Looking near
zero fields

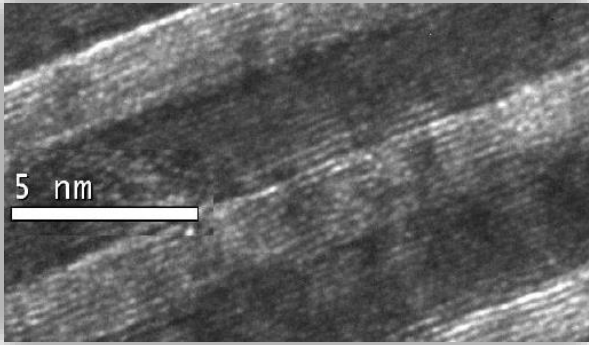


$$H_f = \frac{\pi^2 h^2 M_s}{\sqrt{2} \lambda t_{FL}} \exp\left(-2\pi \frac{\sqrt{2} d}{\lambda}\right) \times \left[1 - \exp\left(-2\pi \frac{\sqrt{2} t_{FL}}{\lambda}\right)\right] \times \left[1 - \exp\left(-2\pi \frac{\sqrt{2} t_{RL}}{\lambda}\right)\right]$$

t_{FL} nm	t_{RL} nm	M_s emu/cc	λ nm	h nm
3	3	1466	9.47	0.13

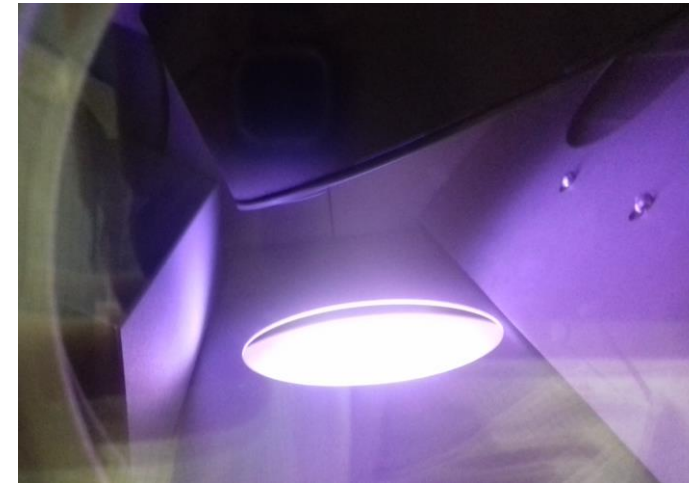
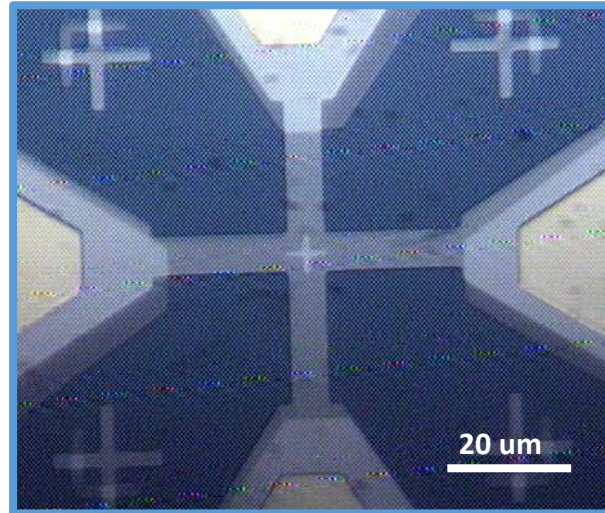


➤ A method to access the MgO/CoFeB roughness.



Film thickness:
Controlled at the atomic scale
 $1 \text{ \AA} = 0.1 \text{ nm}$

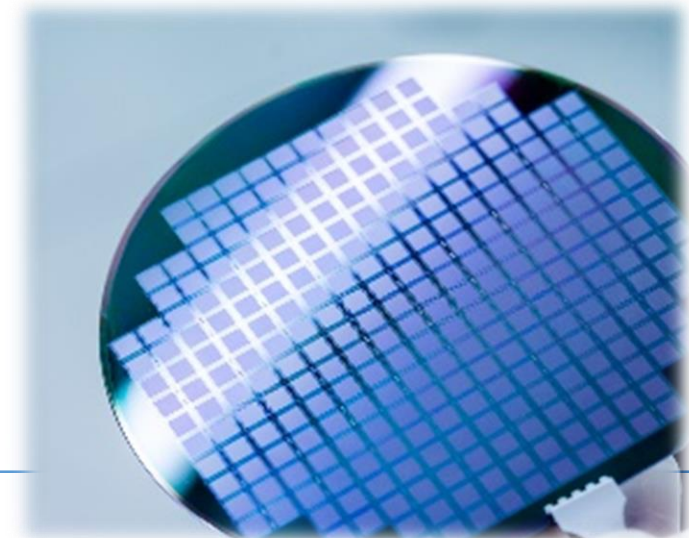
Multilevel device
patterning



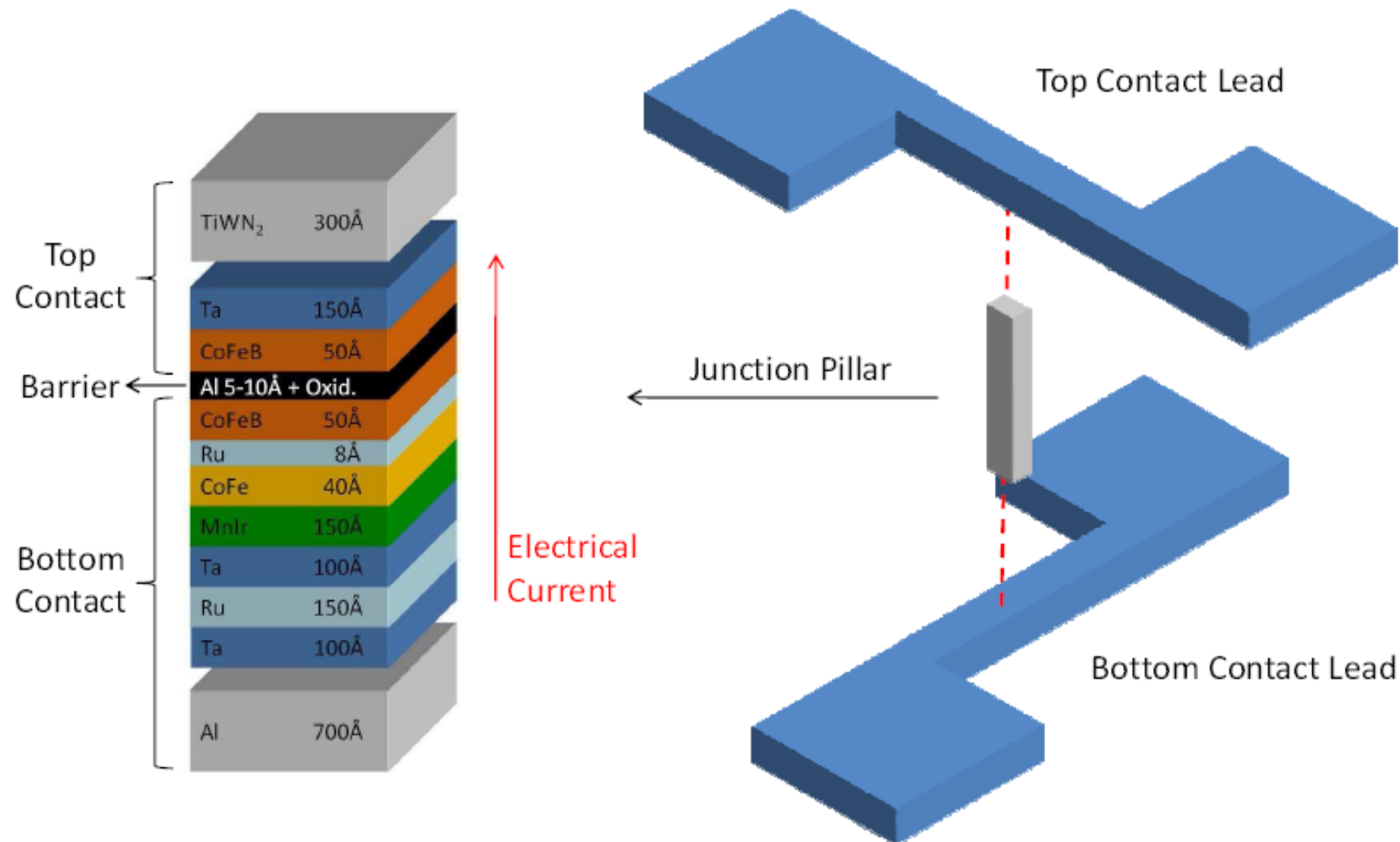
MgO target with Ar plasma



Wafer microfabrication
in a Clean Room



Current-perpendicular-to-plane (CPP) device fabrication



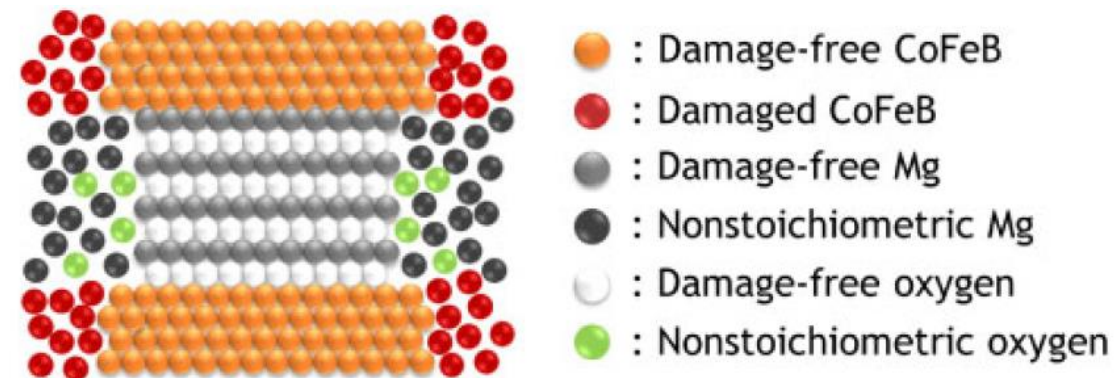
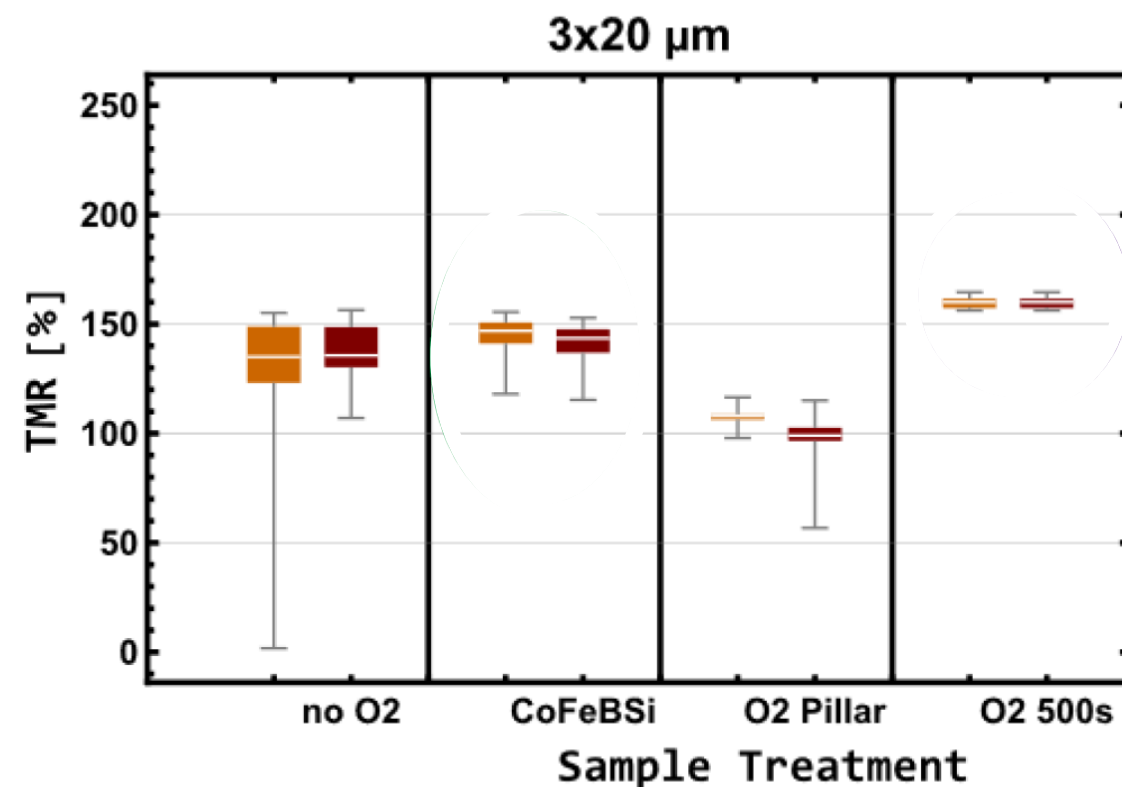
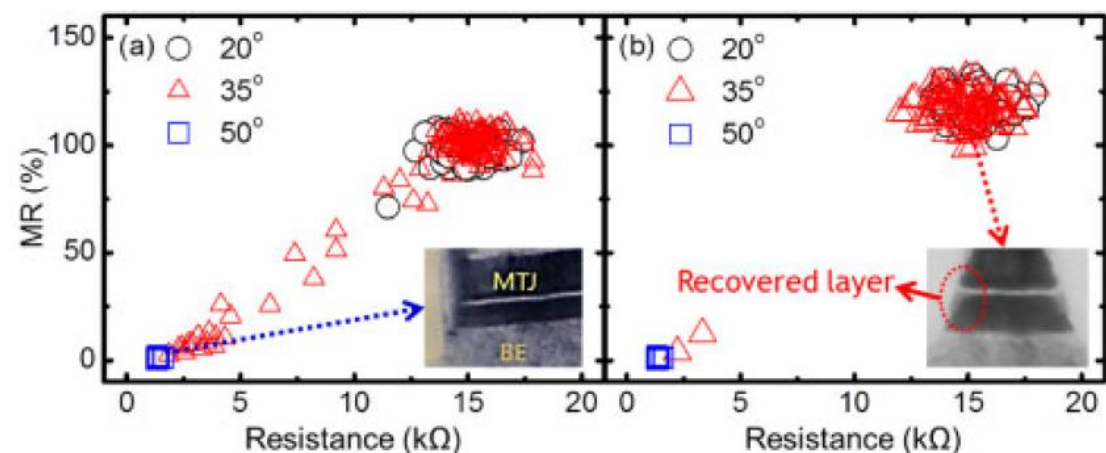


Fig. 5. (Color online) Substance distribution diagram of the patterned MTJs after the etching process.

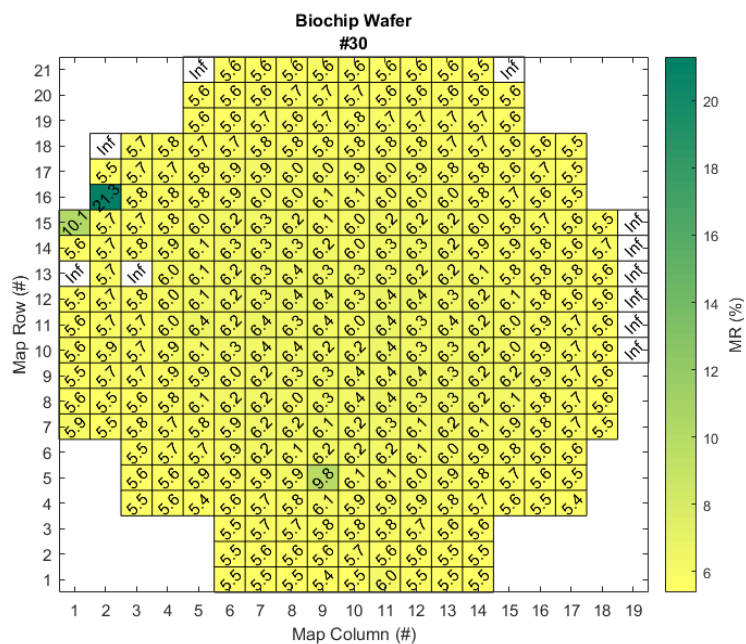


GMR biosensor qualification (6 inch wafers)

Magnetoresistance (%)

Mean = 6.26 %

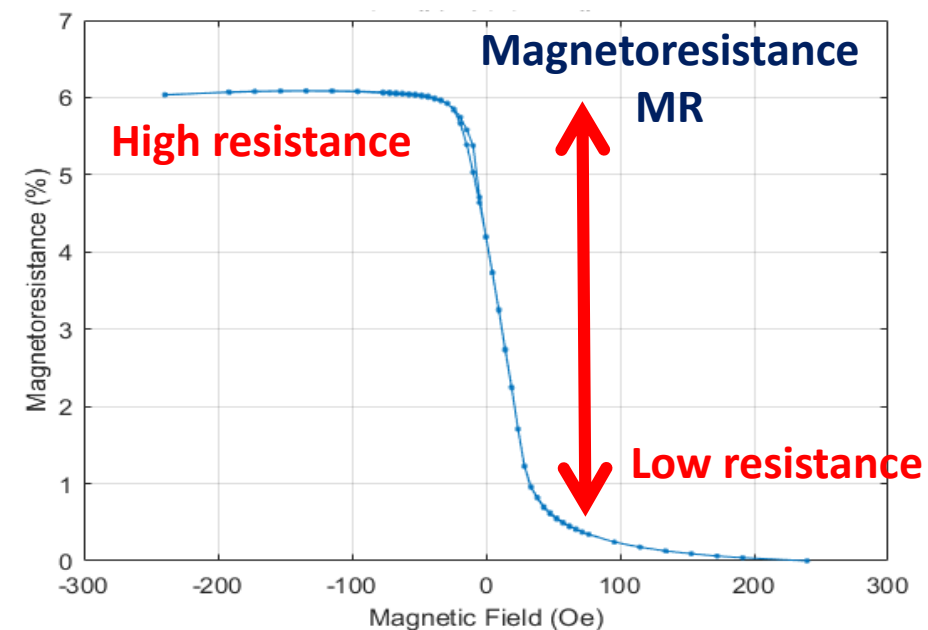
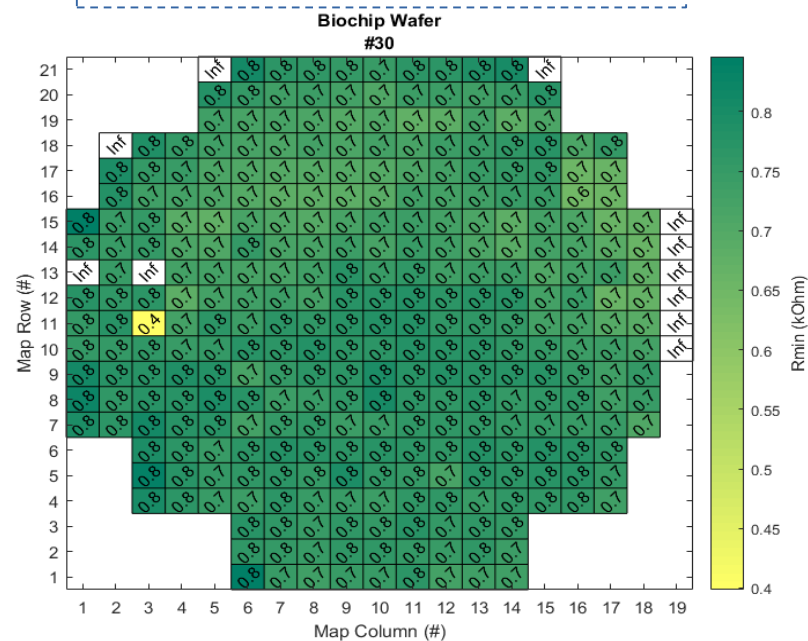
Std = 0.97%



Minimum Resistance (Ω)

Mean = 743.1 Ω

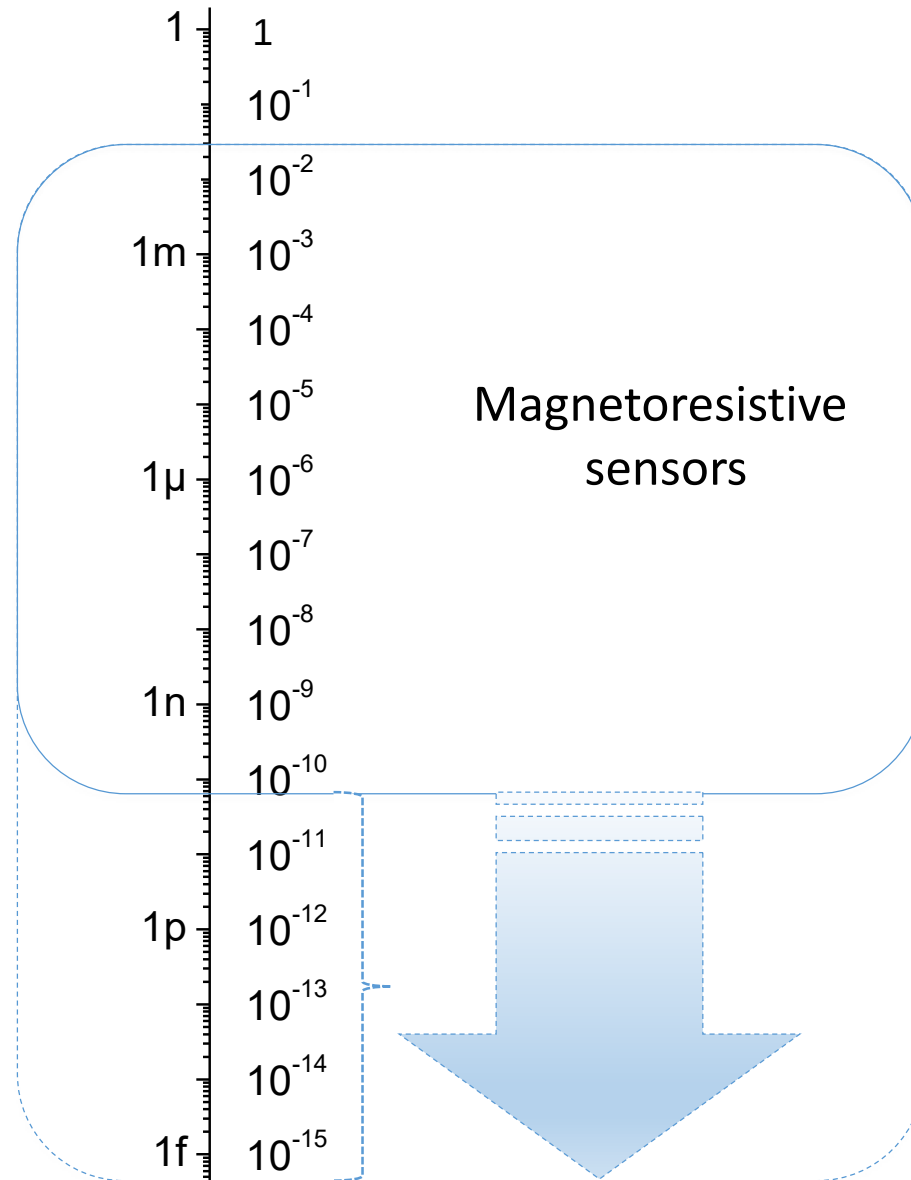
Std = 38.2 Ω



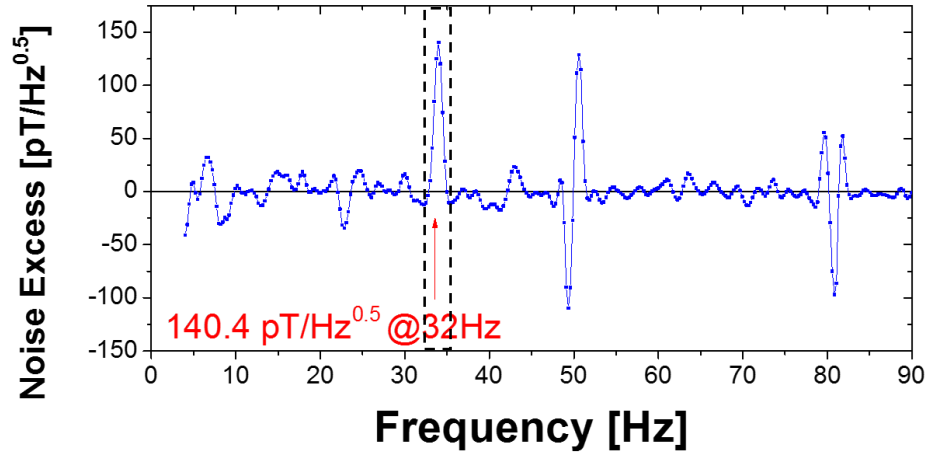
Challenges

- Low fields detection
- Small footprint

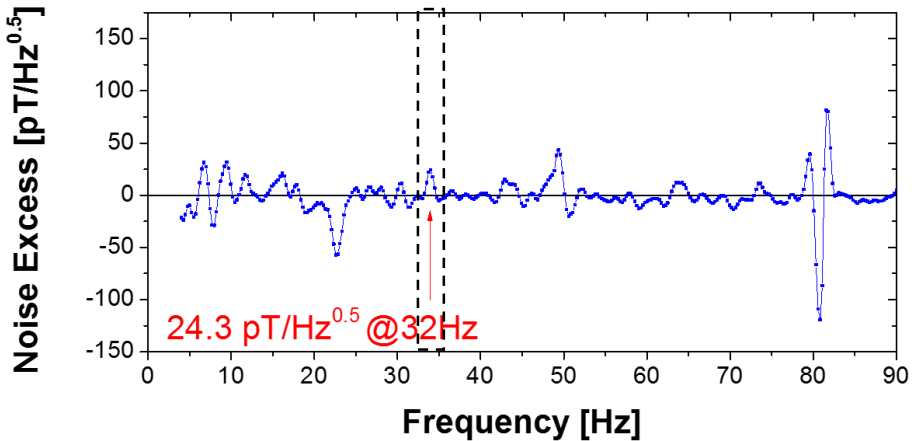
Magnetic Field (Tesla)



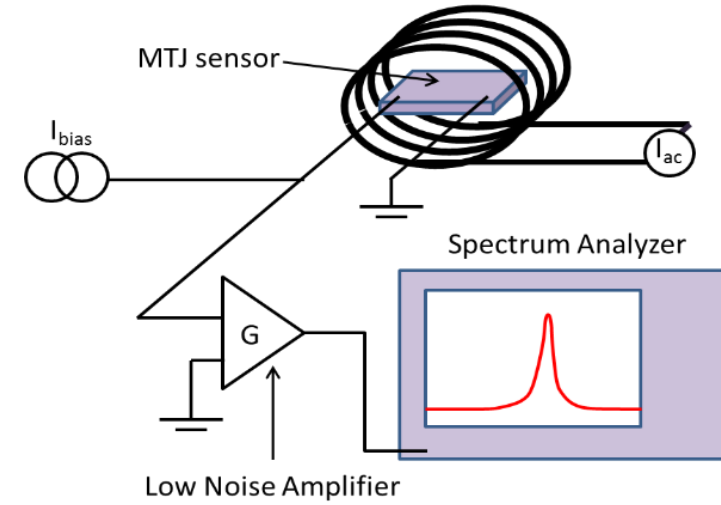
How to distinguish signal from noise ?



Current I_1



Current $I_2 < I_1$

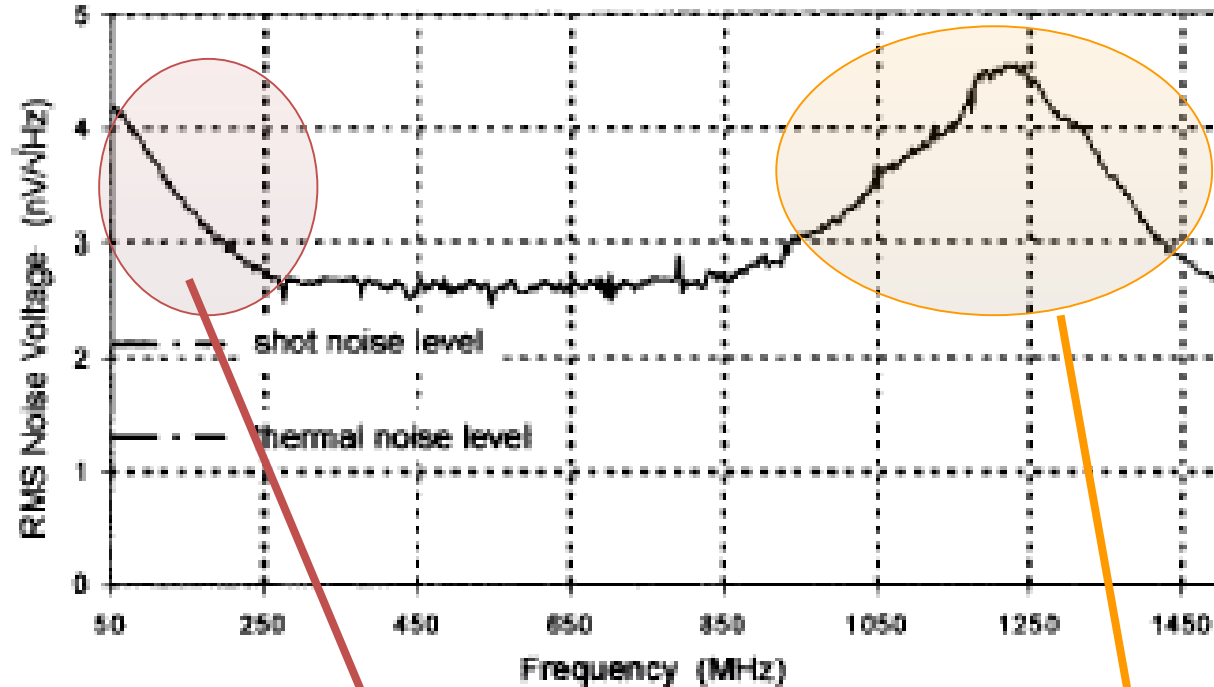


Detectivity limit:

SNR = 1
(Signal = Noise)

Noise Spectrum of Magnetoresistive Sensors

Low f + low field



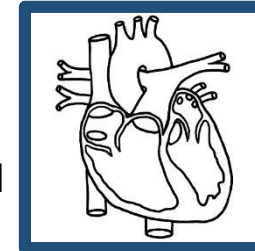
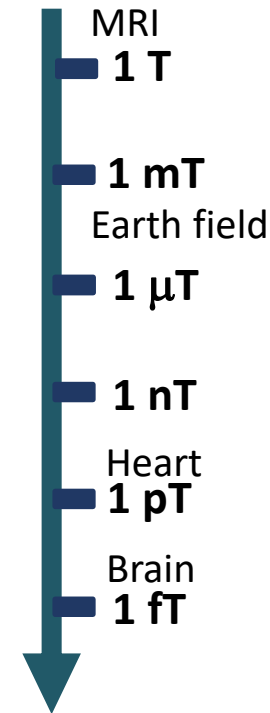
$$S_V(V^2 / \text{Hz}) = \frac{\alpha_H I^2 R^2}{A f \Delta f} + \frac{4 K_B T R}{\Delta f} + \frac{2 e I R^2}{\Delta f} + FMR_{\text{Noise}}$$

1/f noise

Thermal
Noise

Shot
Noise

High-Frequency Noise



Amplitude:

few **pTesla** at chest surface
(below 100 Hz)

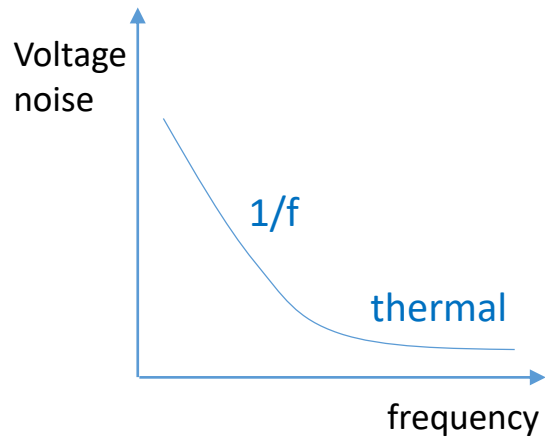
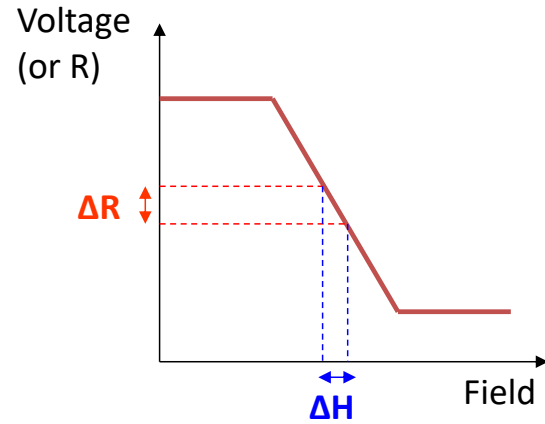


Amplitude:

few **fTesla** at skull surface
(below 100 Hz)

Field detectivity (D)

Detectivity limit: **SNR = 1** (Signal = Noise)



$$S_V \left(T / \sqrt{Hz} \right) = \frac{\sqrt{\frac{\alpha_H I^2 R^2}{A f}}}{I \cdot \frac{\Delta R}{\Delta H}} = \frac{\Delta H}{MR} \sqrt{\frac{\alpha_H}{A f}} \quad [in Tesla]$$

(in 1/f regime)

$S = TMR / \Delta H$
sensor sensitivity

α_H = Hooge's constant
 A = MR area
 f = operating frequency

Operate at high f
Increase MR
Increase A
Reduce linear range ΔH
Reduce Hooge value

Strategies to improve the minimum detectable field

(in 1/f regime)

$$S_V \left(T / \sqrt{\text{Hz}} \right) = \frac{\sqrt{\frac{\alpha_H I^2 R^2}{V f}}}{I \cdot \frac{\Delta R}{\Delta H}} = \frac{\Delta H}{MR} \sqrt{\frac{\alpha_H}{V f}}$$

[in Tesla]



Field modulation for high frequency
Increase TMR
Increase V (area or thickness)
Reduce linear range ΔH
Reduce Hooge value

α_H = Hooge's constant

A = MR area

f = operating frequency

Field modulation

Sensors, 18(3), 790; (2018)

Micromachines, 7(5), 88 (2016)

IEEE Trans. Magn. 48 (11), pp. 4115 (2012)

Journal of SPIN, Vol.1 (1), pp 71-91 (2011)

J.Appl.Phys. 103, 07E924 (2008)

Appl. Phys. Lett. 95, 023502 (2009)

Improve MR

Nat Mater, 2004, 3:862–867

J PhysD-Appl Phys, 2007, 40: R337

J. Physics: Cond.Matter, 19 (2007) 165221

Ann Rev Mater Res, 2009, 39: 277–296

J Appl Phys, 2007, 101: 09B501

J. Appl. Phys, 99, 08A907 2006

Reduce α_H

IEEE Trans. Magn. 51, 1 (2015)

IEEE Trans. Magn. 50, 1 (2014)

Microsys. Technol. 20, 793 (2014)

Increase A

APL, 91, 102504 (2017)

JAP; 115. 2014

AIP Advances 8(5):056644 (2018)

Scientific Reports, 11, 215 (2021)

IEEE Trans. Magn. 48, 4111 (2012)

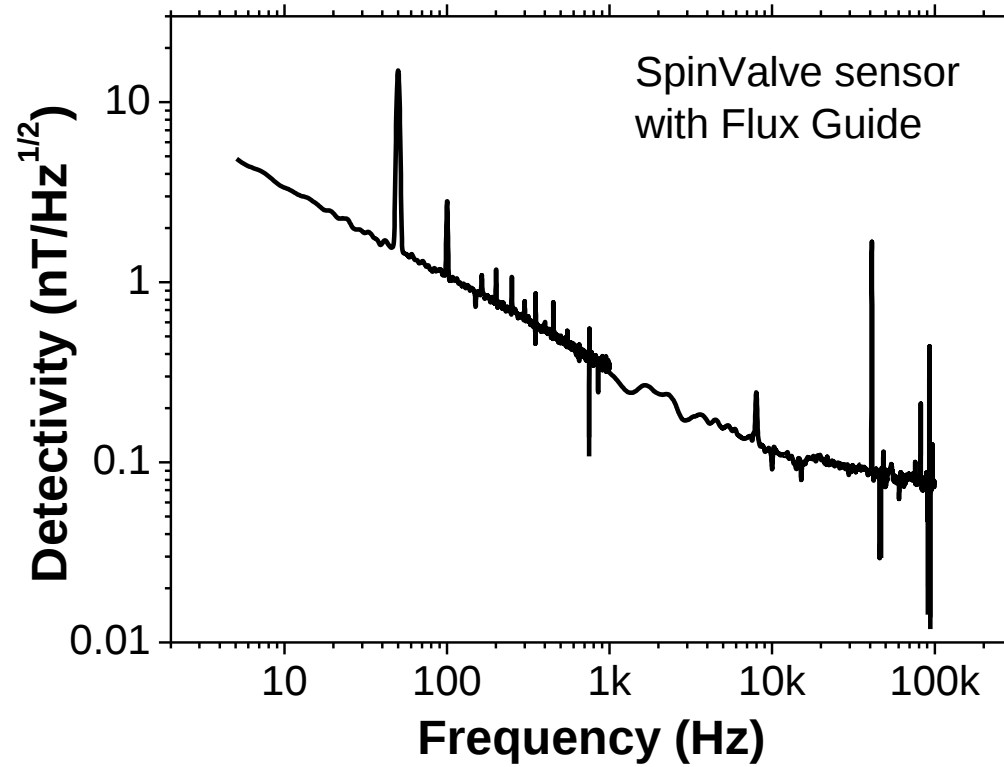
Reduce linear range

IEEE Trans. Magn. 48 (11), pp. 3847 (2012)

J.Appl.Phys.109, pp.07E521 (2011)

IEEE Trans Magn. 50 (11), 4003805 (2017)

IEEE Trans Magn. 55, 7, 4400605 (2019);

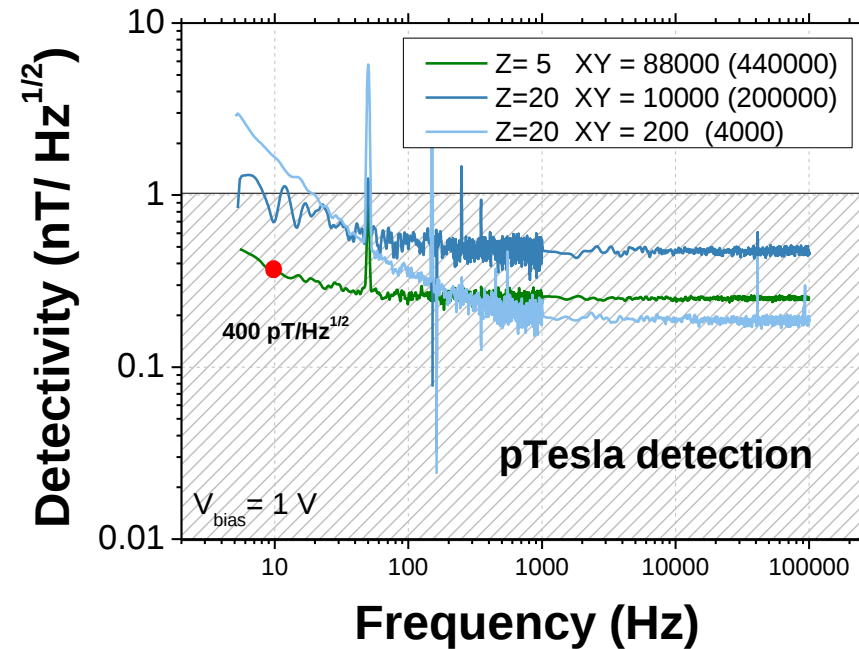
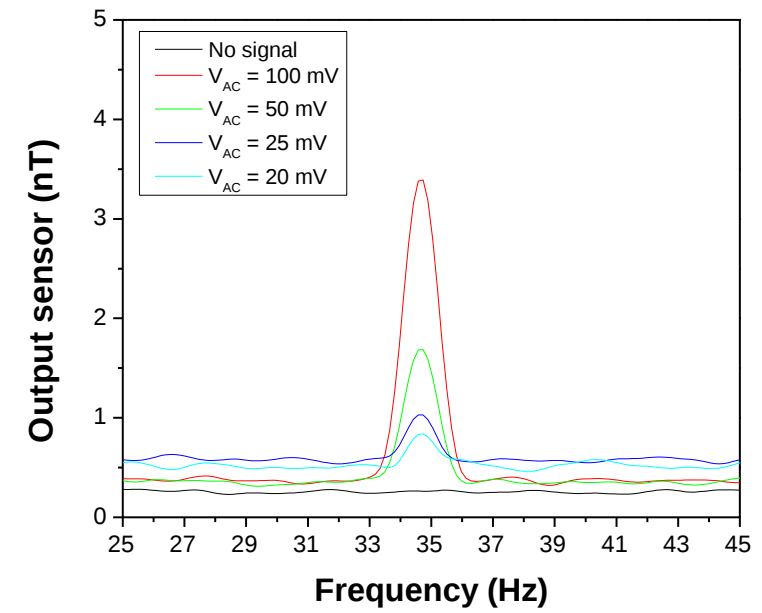


Detectivity values:

3.3 $\text{nT}/\text{Hz}^{1/2}$ @ 10 Hz

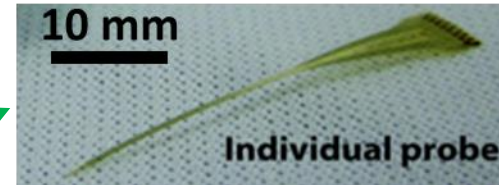
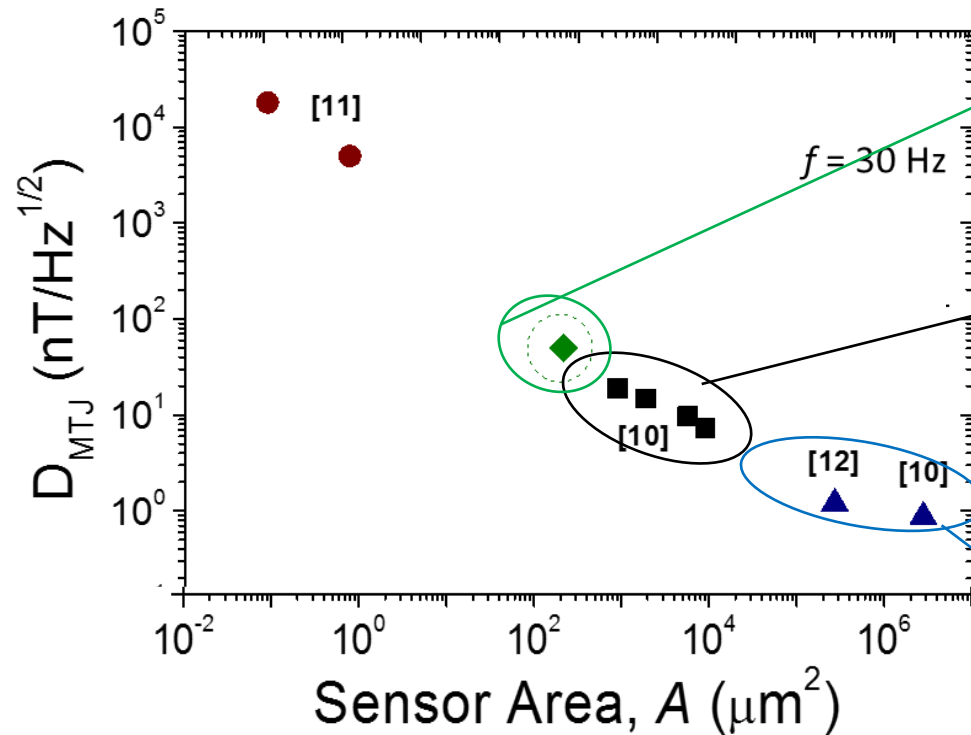
1.9 $\text{nT}/\text{Hz}^{1/2}$ @ 30 Hz

310 $\text{pT}/\text{Hz}^{1/2}$ @ 1 kHz

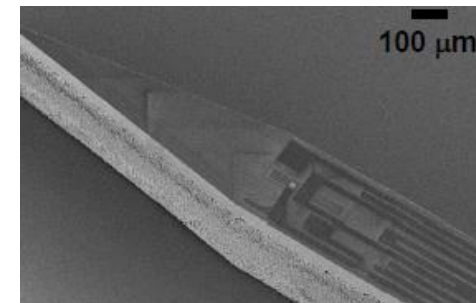


Detectivity (D) - minimum detectable field

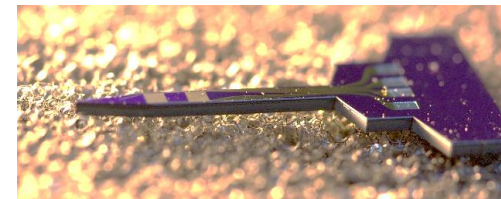
$$SNR = 1$$



flexible probe - polyimide



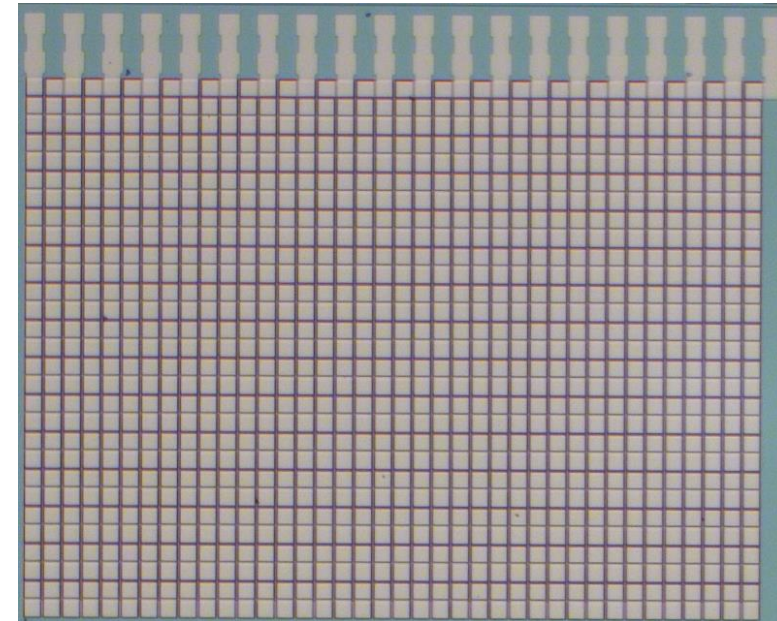
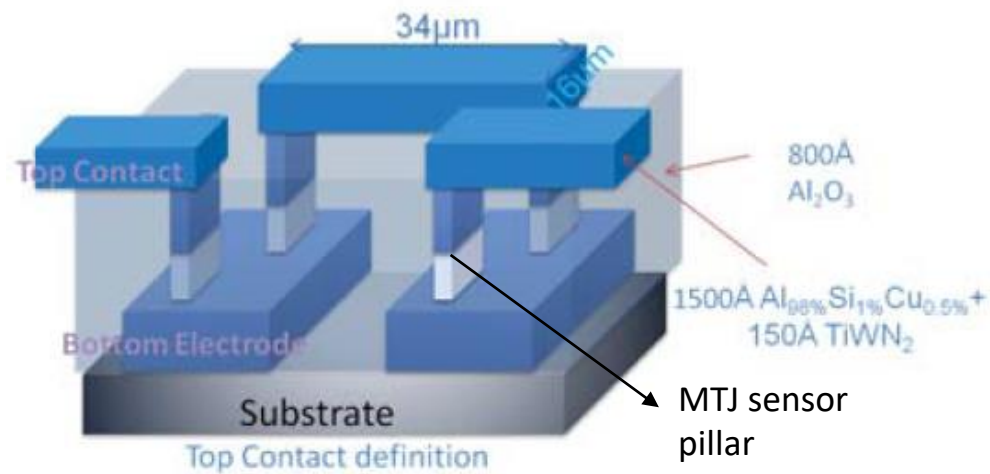
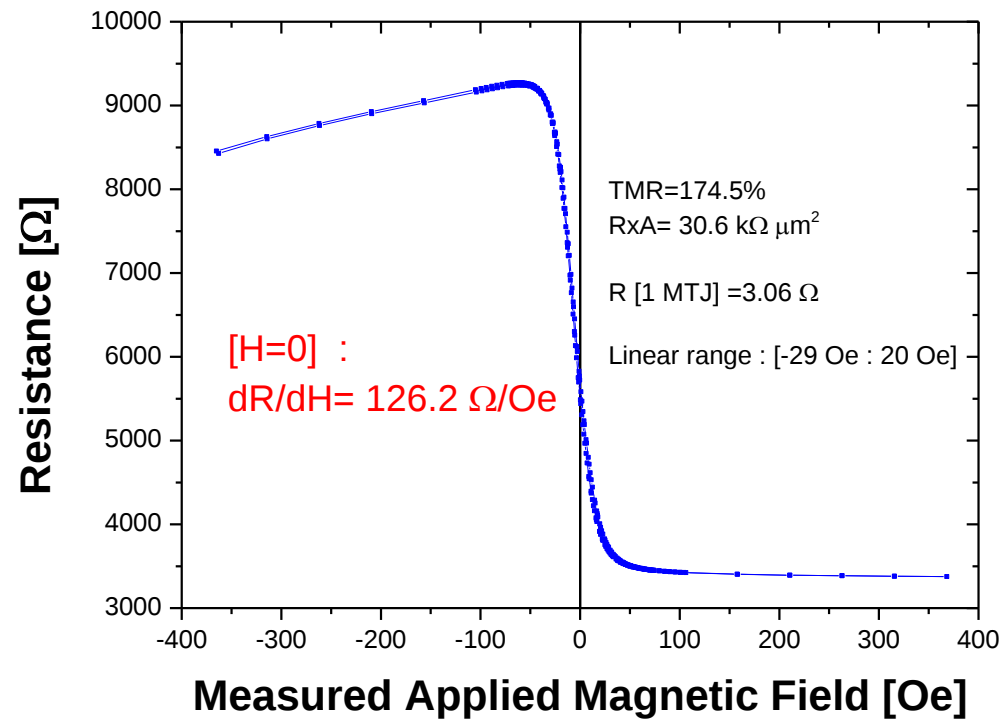
Si probe (single MR)



Si probe (arrays MR)



Large Series 1102 TMR elements with $A = 100 \times 100 \mu\text{m}^2$ each.



Increase V (area or thickness)

...for people with enough space



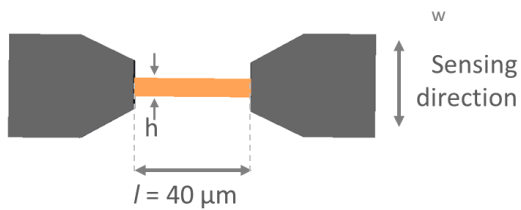
...for all others



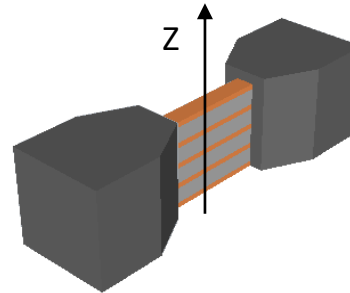
Courtesy: C.Caldeira, Nanium

Saving space: GMR sensors packed

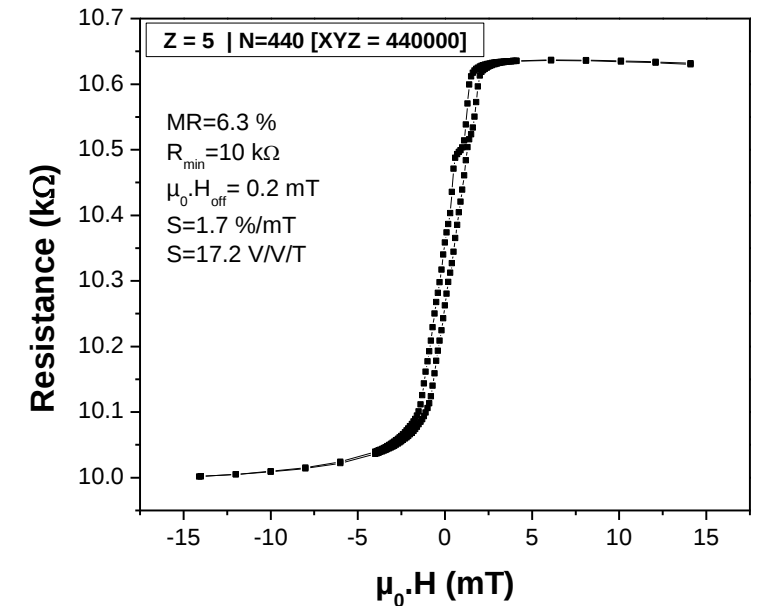
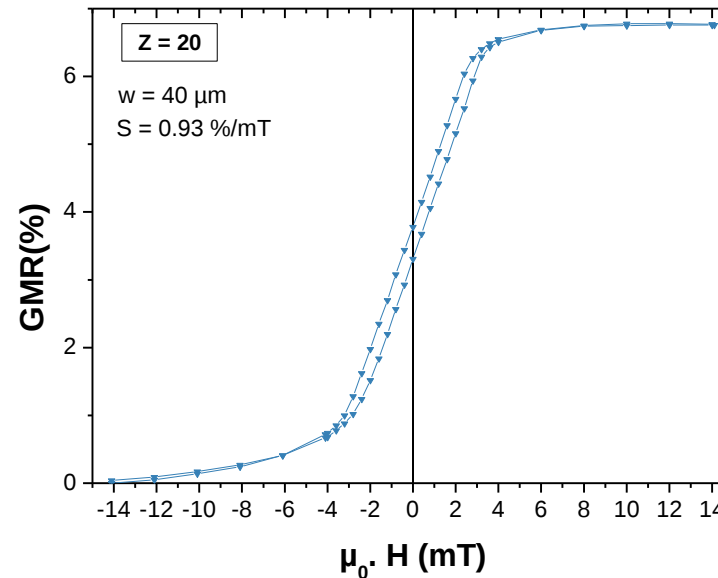
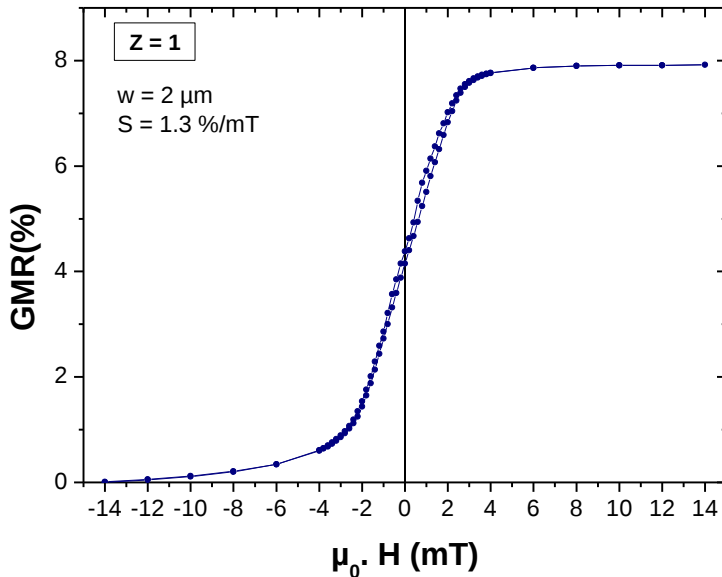
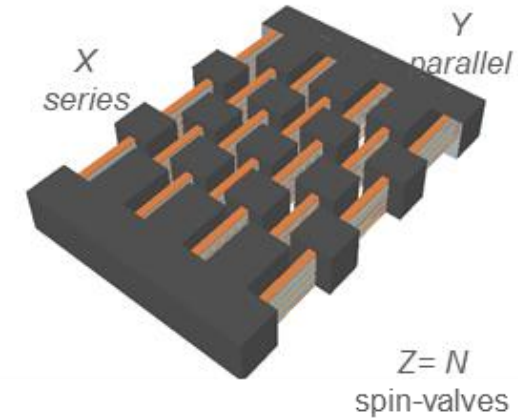
Single sensor



Packed sensors

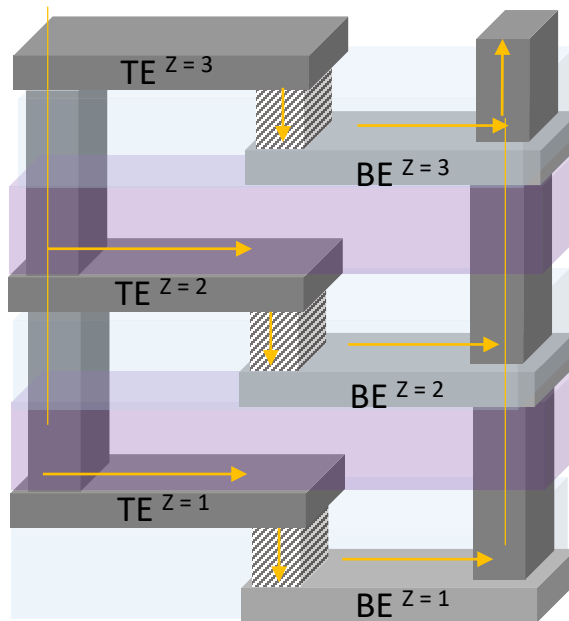


Packed arrays of sensors

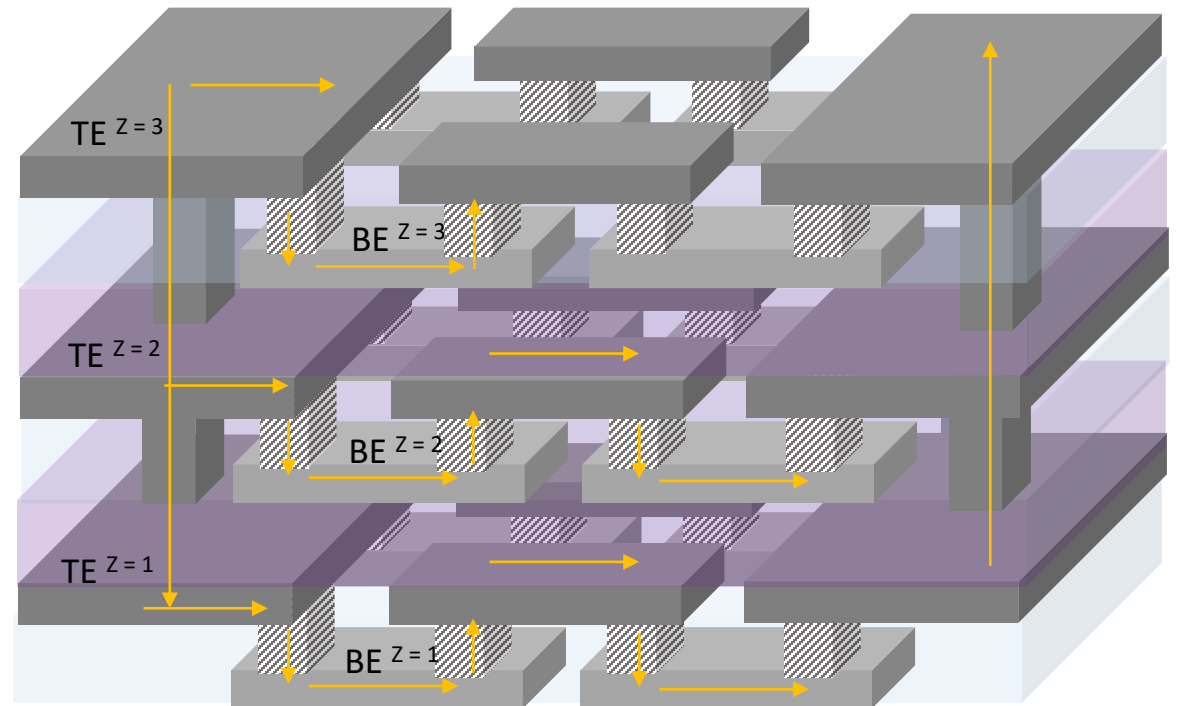


TMR sensors packed

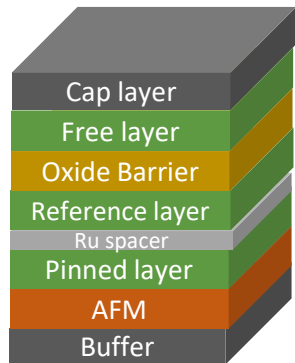
a) Vertical Packed single MTJ

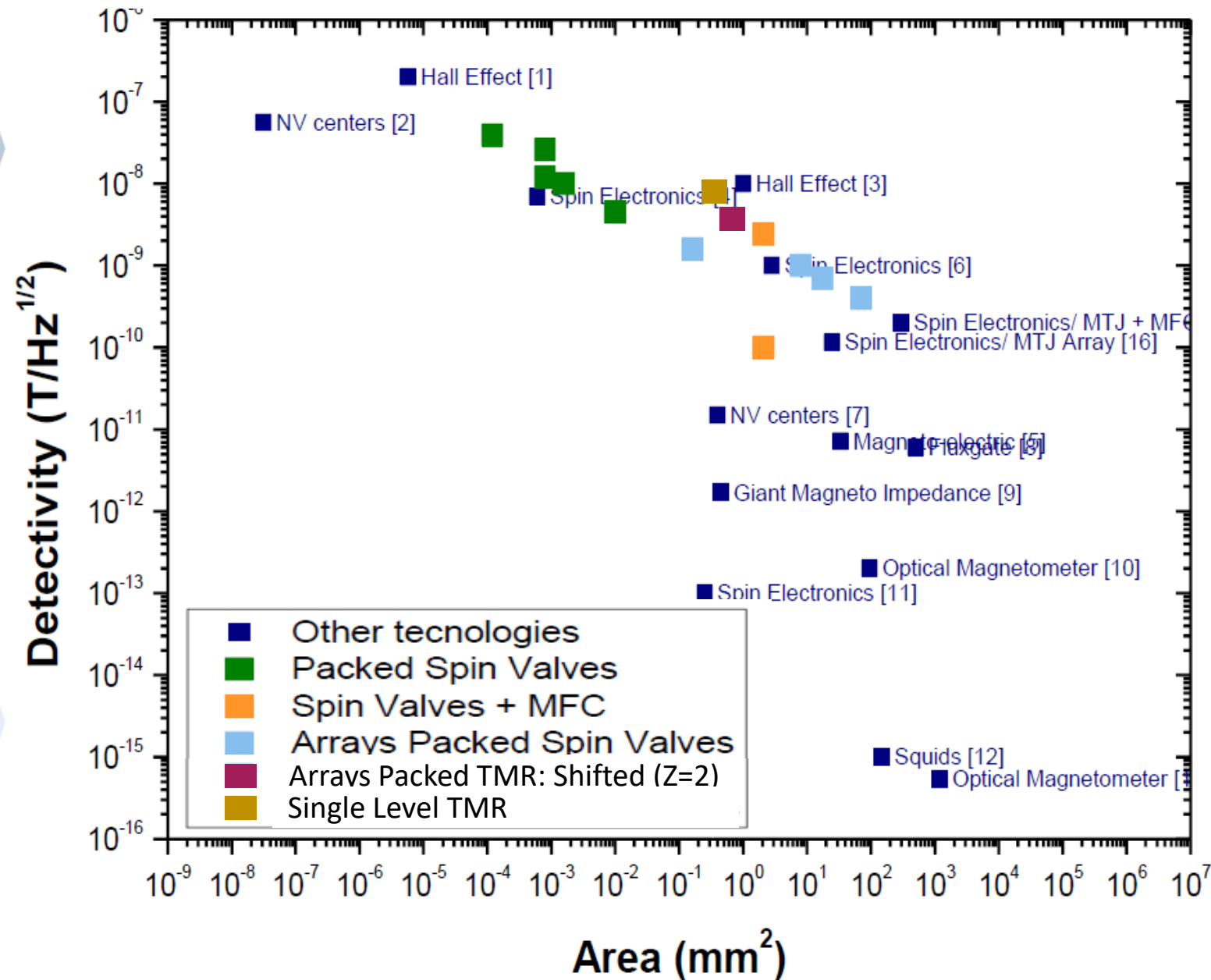


b) Vertical Packed MTJ Array



TMR structure





AIP Advances 8(5):056644 (2018)
Scientific Reports , 11, 215 (2021)

- [1] E. Paz et al., *J. Appl. Phys.*, vol. 115, 2014.
- [2] tdk.com, "TDK biomagnetic sensor", 2019
- [3] S. H. Liou et al., *Proc. IEEE Sensors*, 2009

- [1] P. Besse et al *Appl. Phys. Lett.* **80**, 4199 (2002)
- [2] P. Maletinsky et al *Nature Nanotechnology* **7**, 320-324 (2012)
- [3] F. Montaigne et al *Sensors and Actuators A: Physical* **81**, 324-327 (2000)
- [4] L. Caruso et al *Neuron* **95**, 1283-1291 (2017)
- [5] R. Jahns et al *Sensors and Actuators A: Physical* **183**, 16-21 (2012)
- [6] F. Barbieri et al *Scientific Reports* **6**, 39330 (2016)
- [7] J. Barry et al *PNAS* **113**, 14133-14138 (2016)
- [8] Bartington Instruments, Mag-03 Three-axis
- [9] S. Yabukami et al *JMMM* **290**, 1318-1321 (2005)
- [10] T. Sander et al *Biomedical Optics Express* **3**, 981-990 (2012)
- [11] M. Pannetier et al *Science* **304**, 1648-1650 (2004)
- [12] J. Gallop *Supercond. Sci. Technol.* **16**, 1575 (2003)
- [13] I. Kominis et al *Nature* **422**, 596-599 (2003)
- [14] E. Paz et al., *J. Appl. Phys.*, vol. 115, 2014.
- [15] tdk.com, "TDK biomagnetic sensor", 2019
- [16] S. H. Liou et al., *Proc. IEEE Sensors*, 2009



Challenges II

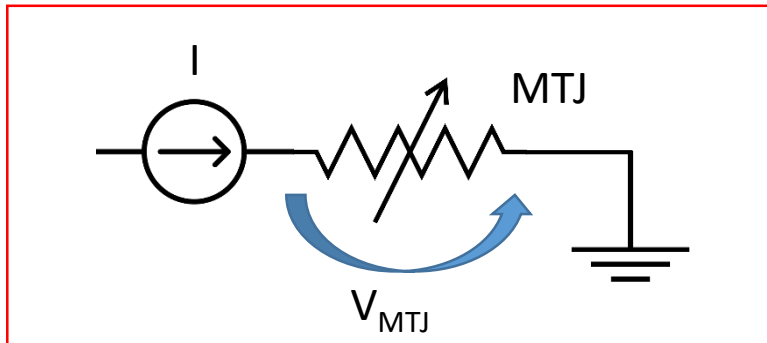
- Wheatstone Bridge architecture
- Thermal stability

CHALLENGE: WHEATSTONE BRIDGE



TMR sensor acts as a variable resistor

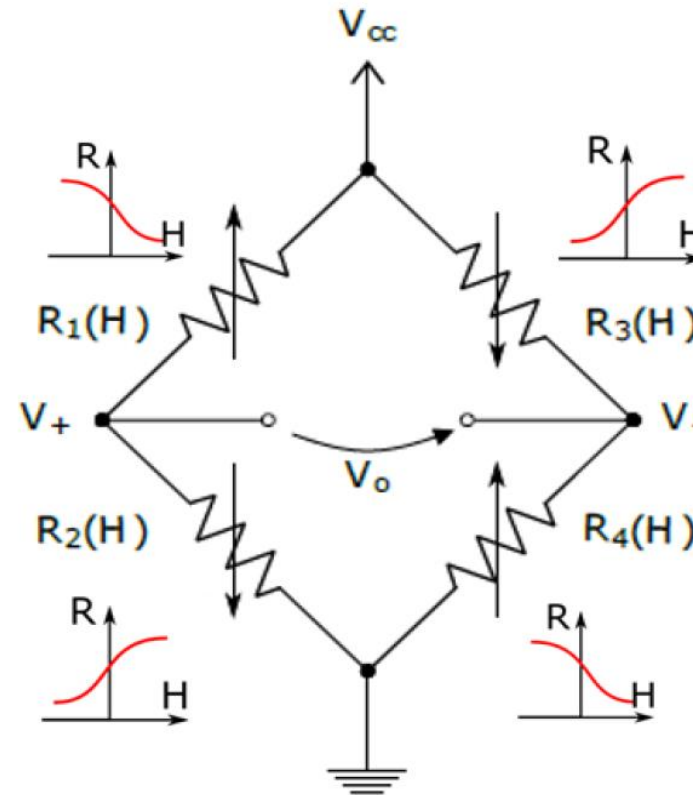
Simplest way to measure:



Disadvantages:

- Current source is difficult to implement
- Prone to supply noise
- Output is not zero when field is zero

Wheatstone bridge



$$V_o = \left(\frac{R_2(H)}{R_1(H) + R_2(H)} - \frac{R_4(H)}{R_3(H) + R_4(H)} \right) V_{cc}$$

Advantages:

- Bipolar output
- Noise immunity
- Easy biasing (V const)

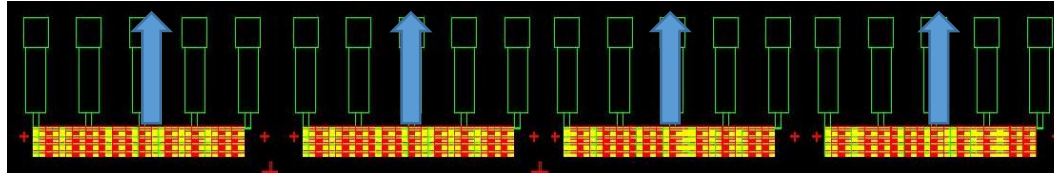
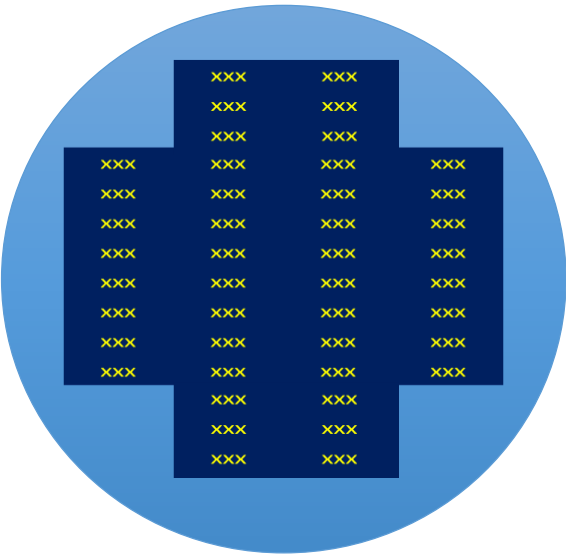
Disadvantage:

- Requires 4 TMR sensors
- **Anti-parallel sensitivities**

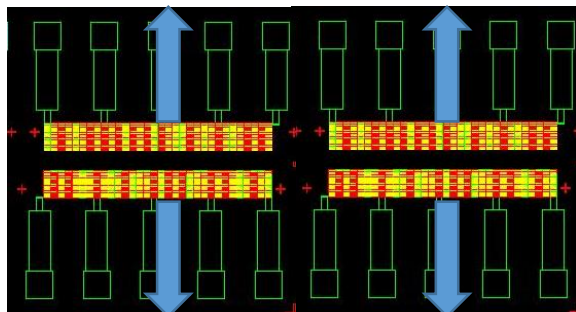
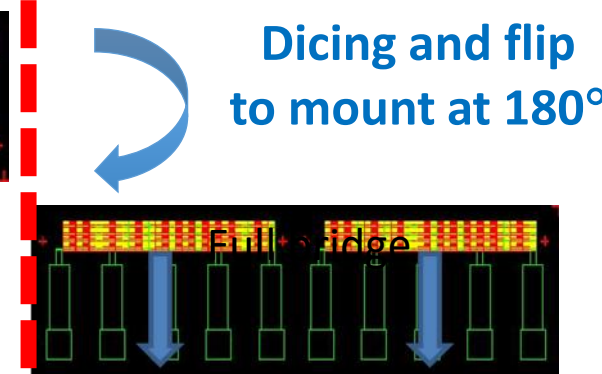
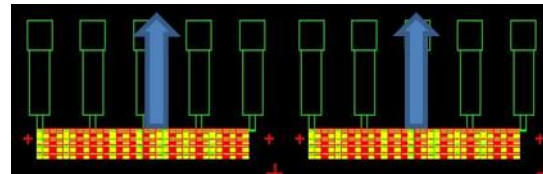


2 reference directions for X
2 reference directions for Y
in the same die

Full bridge with mechanical mounting



1 deposition step for TMR definition
The same annealing for all wafer



Full Wheatstone Bridge

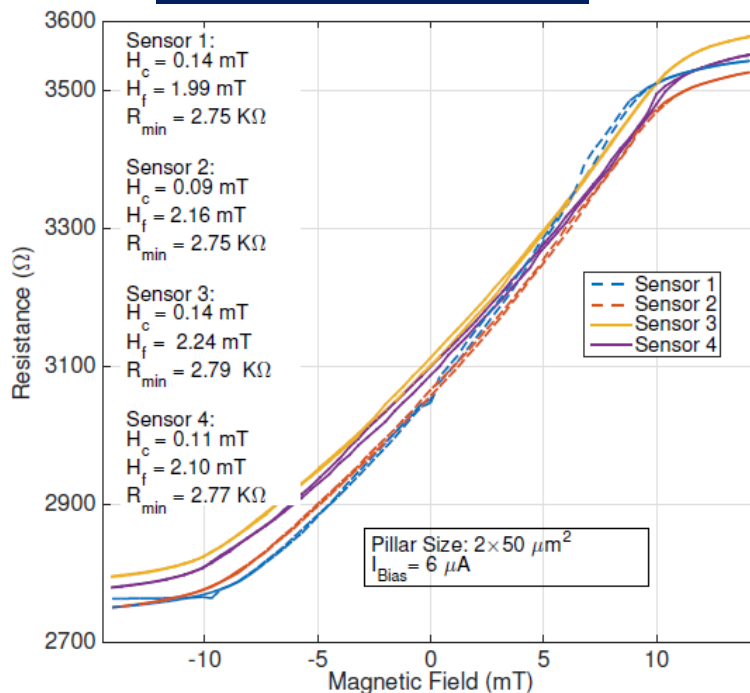
WHEATSTONE BRIDGE — DISCRETE COMPONENT ASSEMBLY

1 direction

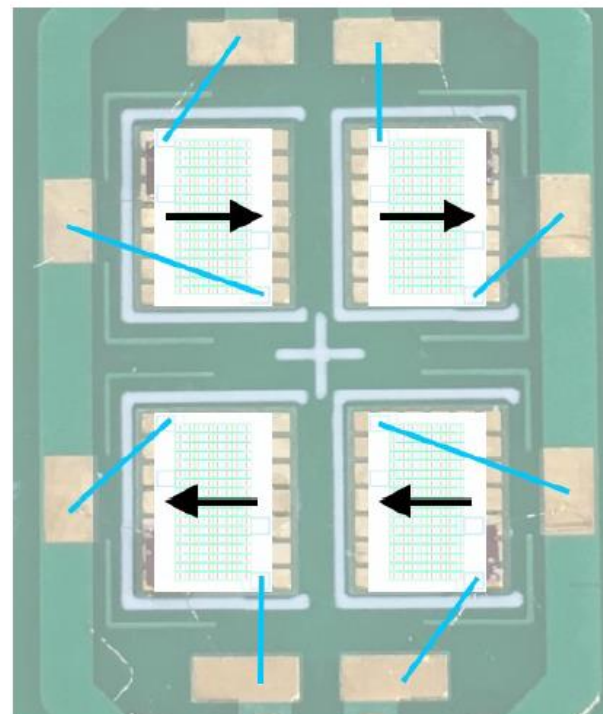


1
deposition

Individual sensors



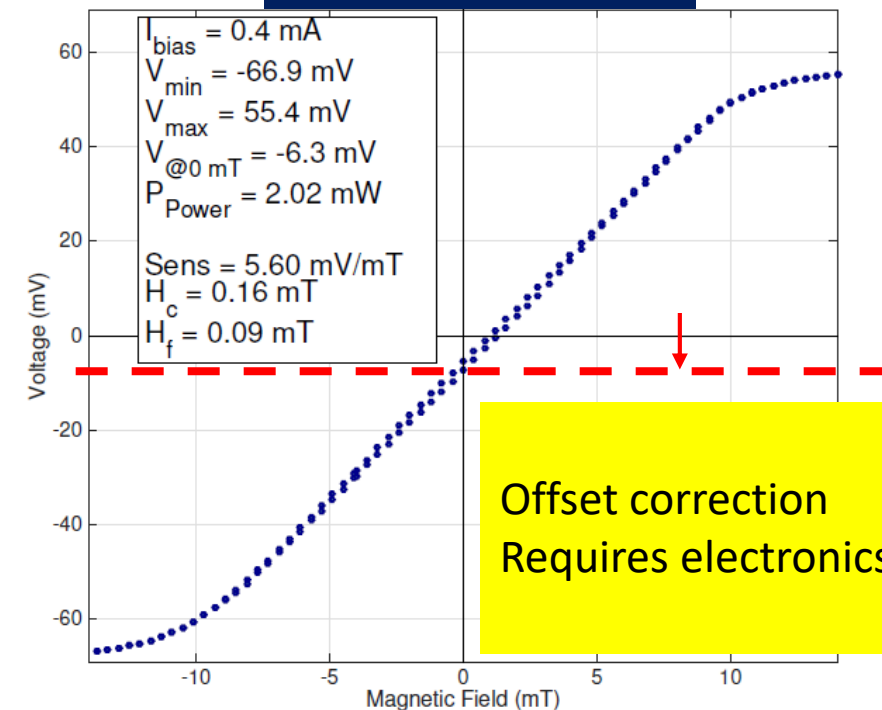
(a) Output of the four sensors that compose the bridge after annealing.



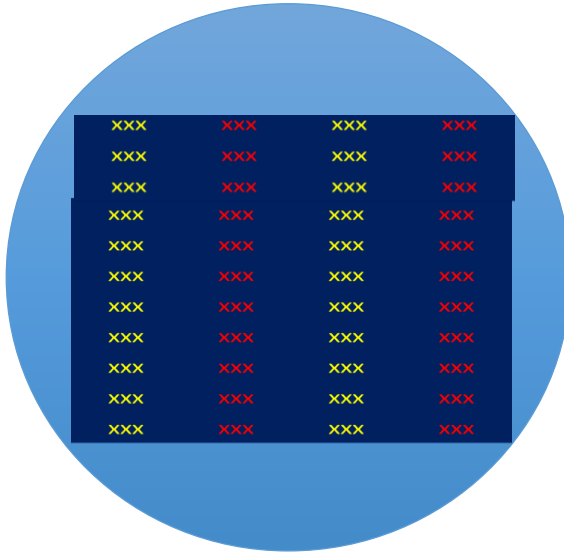
4 AIOx chips mounted in
Wheatstone Bridge

Each chip = $225 \times (2 \times 50 \text{ } \mu\text{m}^2)$

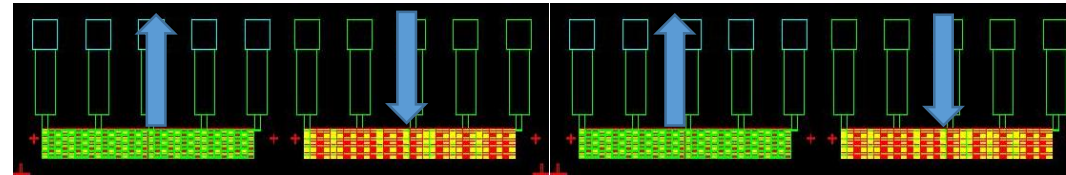
1D Wheatstone bridge



Full bridge with 2 depositions



2 deposition steps for TMR definition

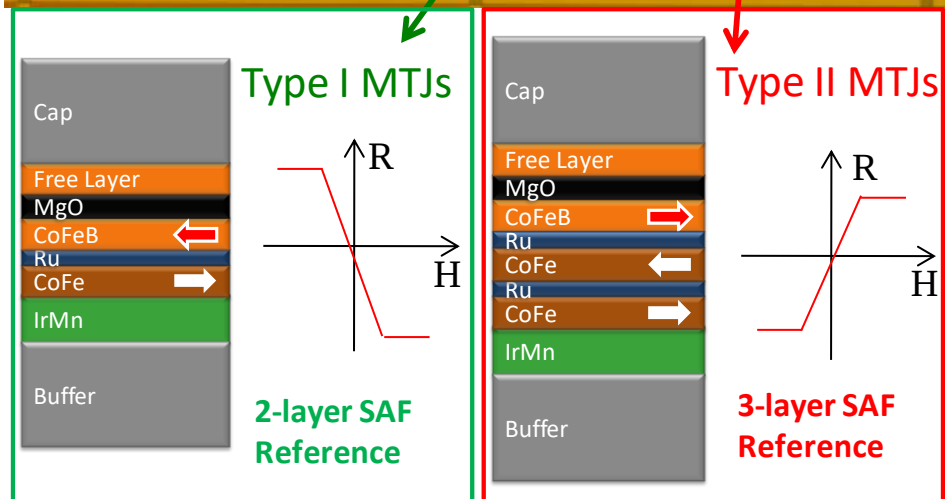
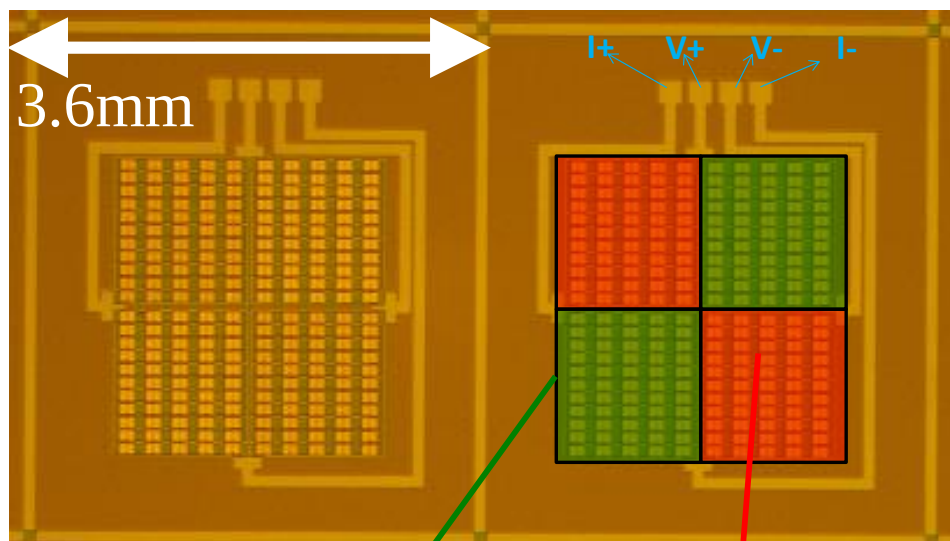


WHEATSTONE BRIDGE — 180° REFERENCE LAYERS

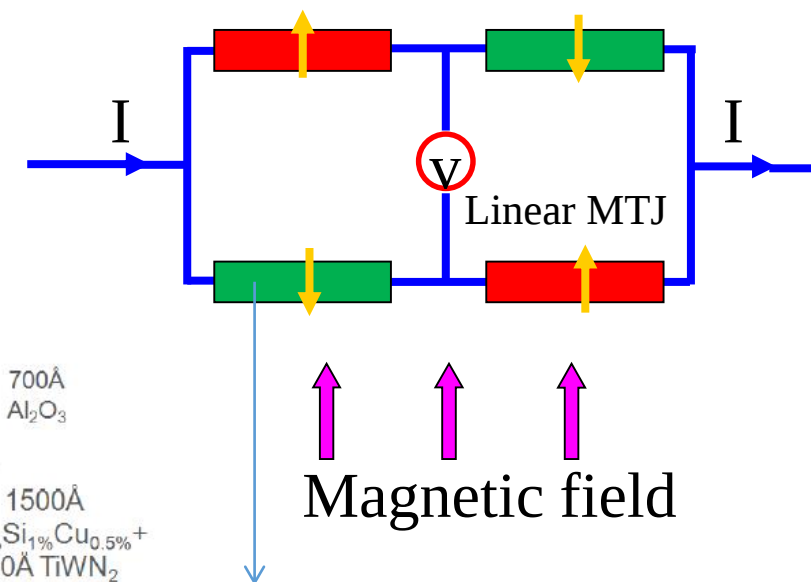
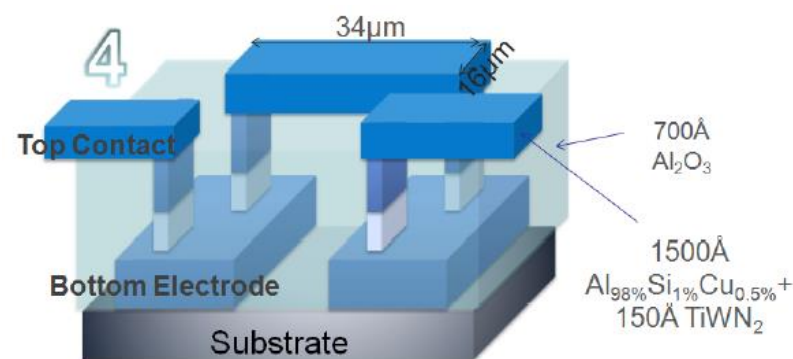
2 directions



2 deposition



1D Wheatstone bridge

Individual MTJ Area: $5 \times 70 \mu\text{m}^2$

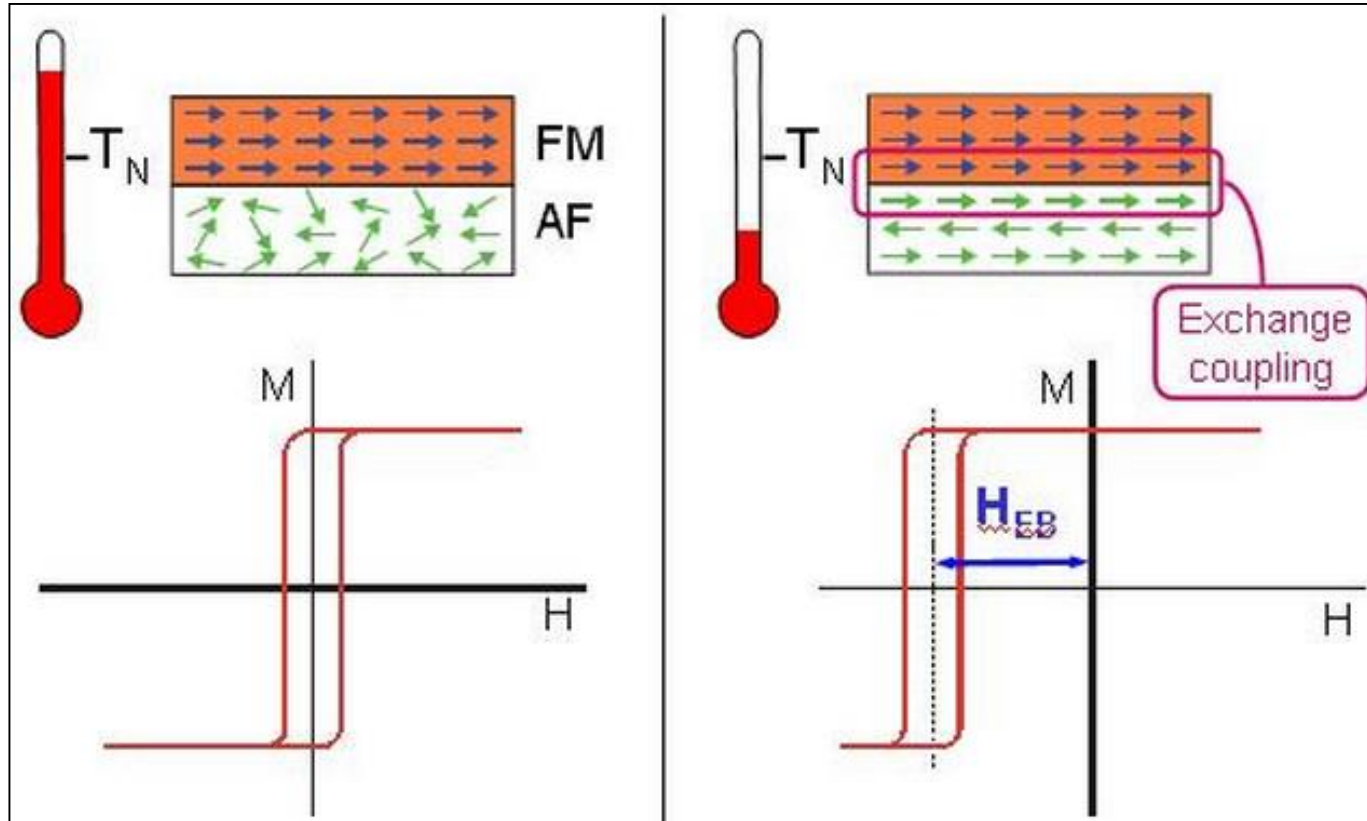
MTJ Elements in series: 110 per arm

Annealing at 330°C required for both TMR stacks at wafer level

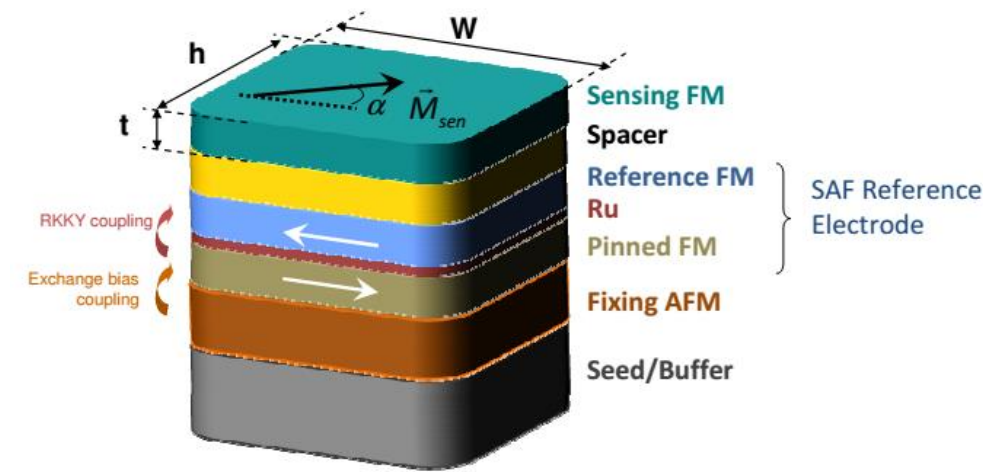
Appl.Phys.Letters 118, 072401 (2021)

IEEE Transactions on Magnetics 48, 4107 (2012)

Exchange coupling – Hysteresis loop



Antiferromagnet:
MnIr, MnPt, MnNi, NiO...



Simple Model

$$E = \frac{1}{2}nJ_{ex}S_F S_{AF} + M_F t_F H$$

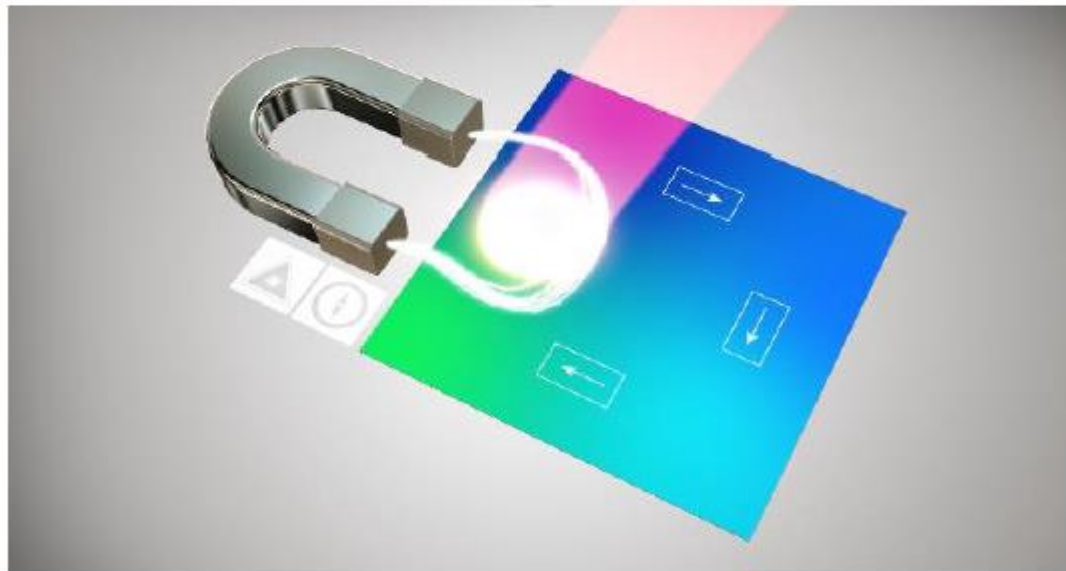
$$H_b = \frac{nJ_{ex}S_F S_{AF}}{2M_F t_F}$$

n - number of interfacial spins per unit area;
 J_{ex} - exchange constant at the interface.

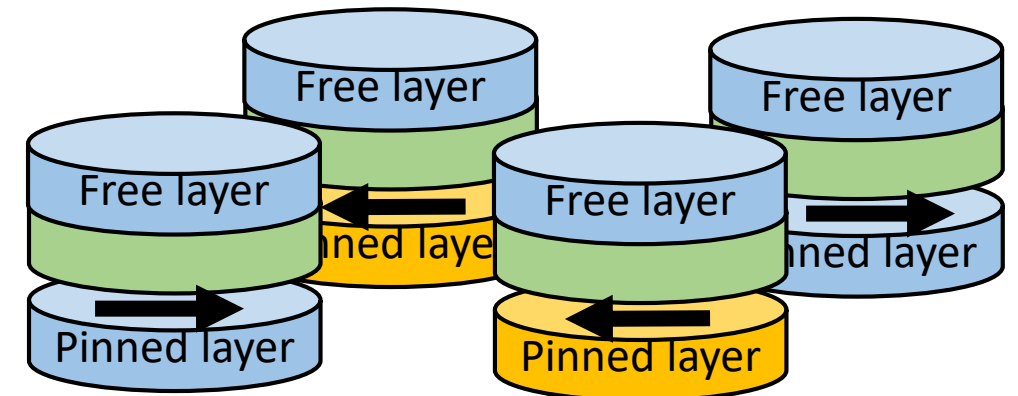
Wafel level laser repining

INESC MN

1
deposition



infrared laser $\lambda = 1064 \text{ nm}$
Spot size $\sim 10 \mu\text{m}$
pulse duration $\sim 100 \text{ ns}$



What is the best temperature to reverse the pinned layer?

Sci Rep 11, 14104 (2021).

IEEE Trans. Magn. 51(1) 4002404 (2017)

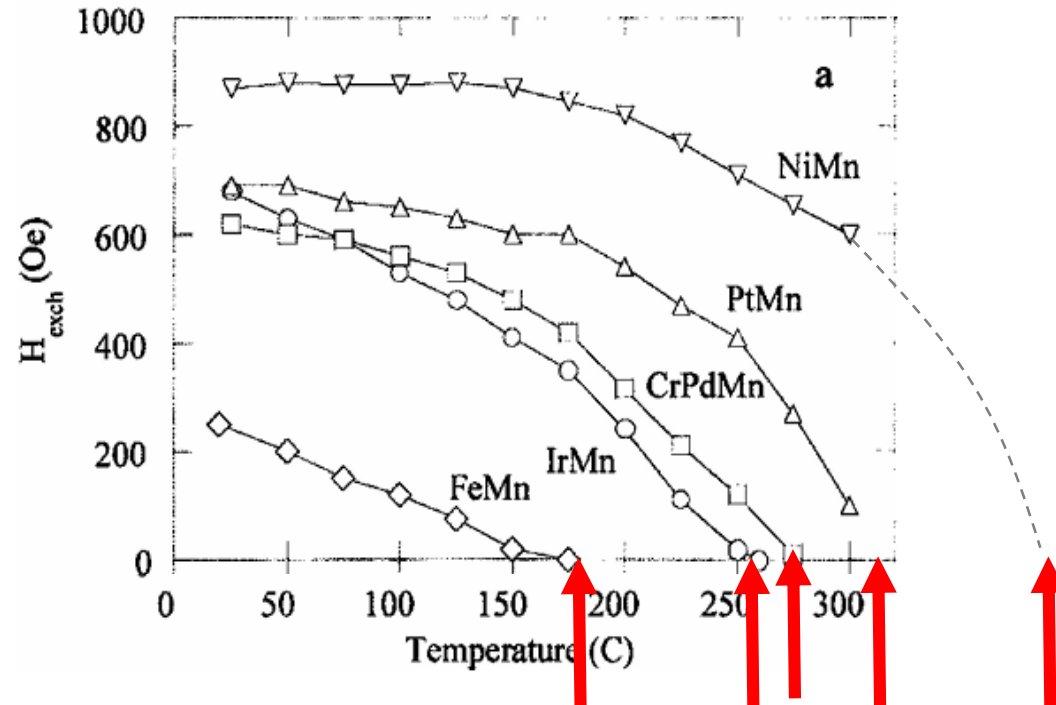
Appl. Surface Science 302, pp. 159–162 (2014)

Selecting the AF material

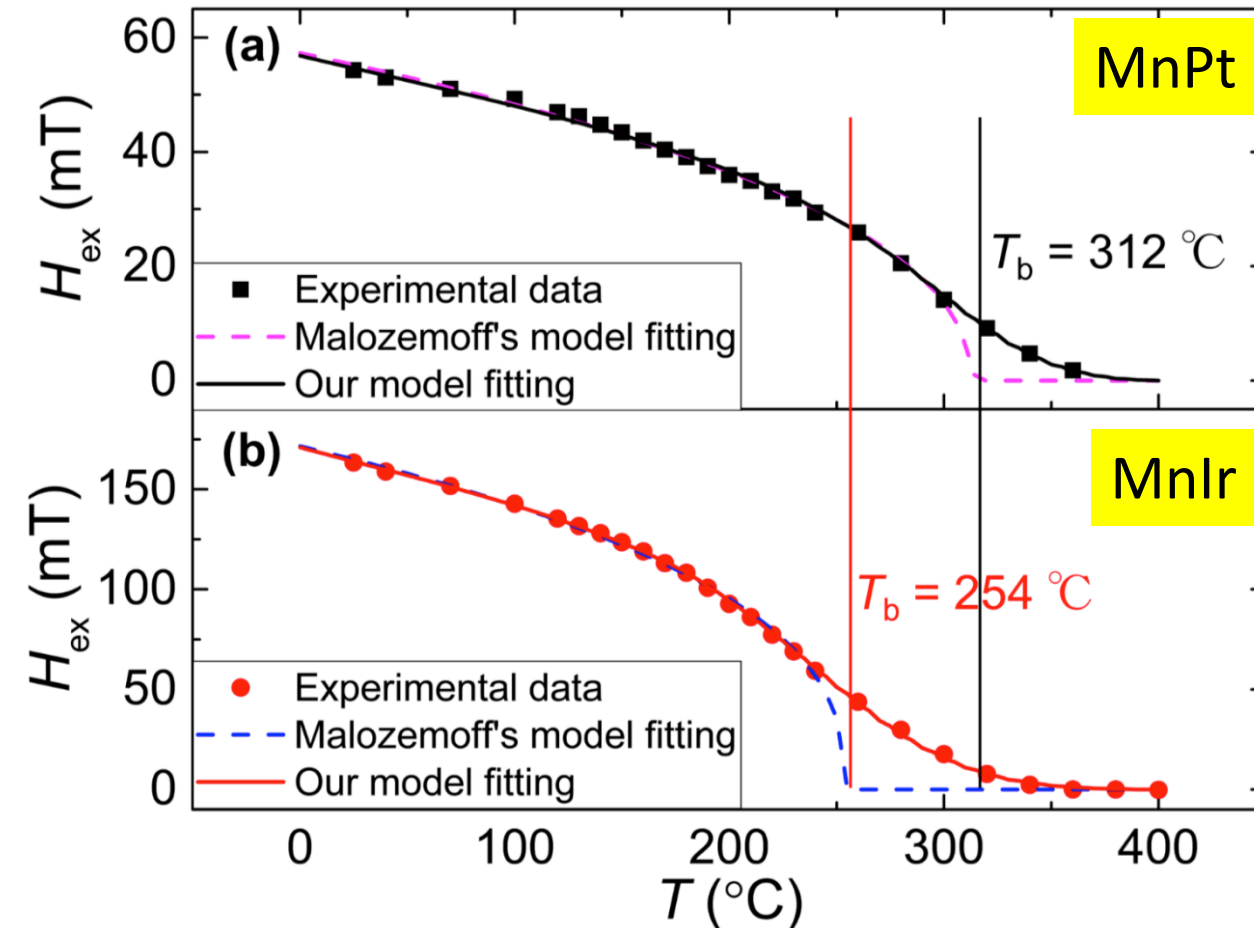
Low T_B



Easier laser repining



Selecting the repining T for each AF material



Malozemoff's Model:

$$H_{ex}(T) = \frac{J_{int}^0}{M_{FM}t_{FM}}j(T) = H_{ex}^0j(T)$$

$$j(T) = \begin{cases} \left(1 - \frac{T}{T_b}\right)^\gamma & : T < T_b \\ 0 & : T \geq T_b \end{cases}$$

Including T_b distribution :

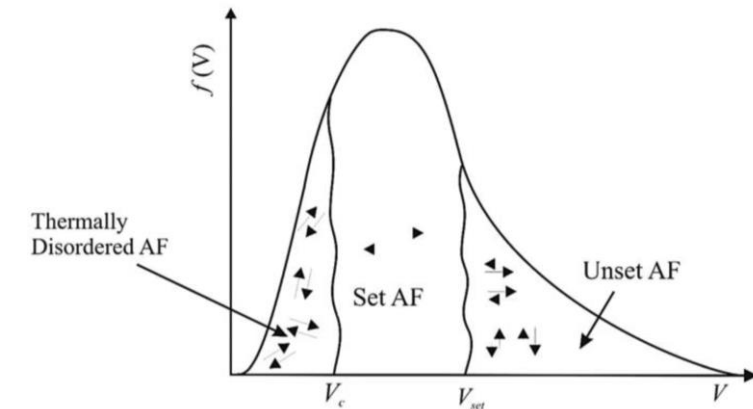
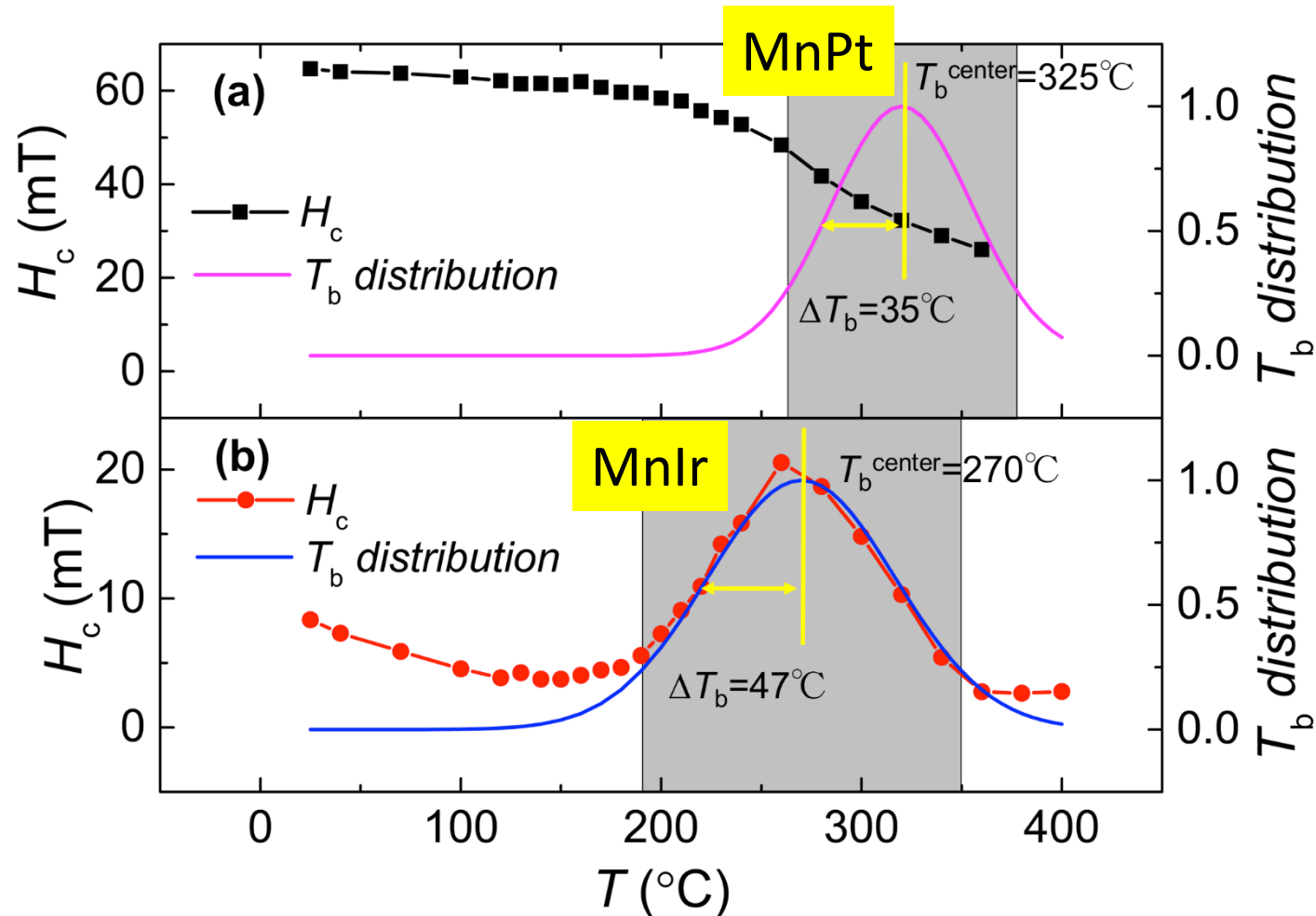
$$H_{ex}(T) = \frac{H_{ex}^0}{1 - \left(\frac{T}{T_c}\right)^{3/2}} \sum_i f(T_{bi}) \begin{cases} \left(1 - \frac{T}{T_{bi}}\right)^\gamma & : T < T_{bi} \\ 0 & : T \geq T_{bi} \end{cases}$$

$$f(T_b^i) = \frac{1}{\Delta T_b \sqrt{2\pi}} \exp \left[-\frac{(T_b^i - T_b^{center})^2}{2(\Delta T_b)^2} \right]$$

Coercivity, T_B distribution

T_B distribution → uncertainty in laser annealing

H_c Model: dependency on the grain size



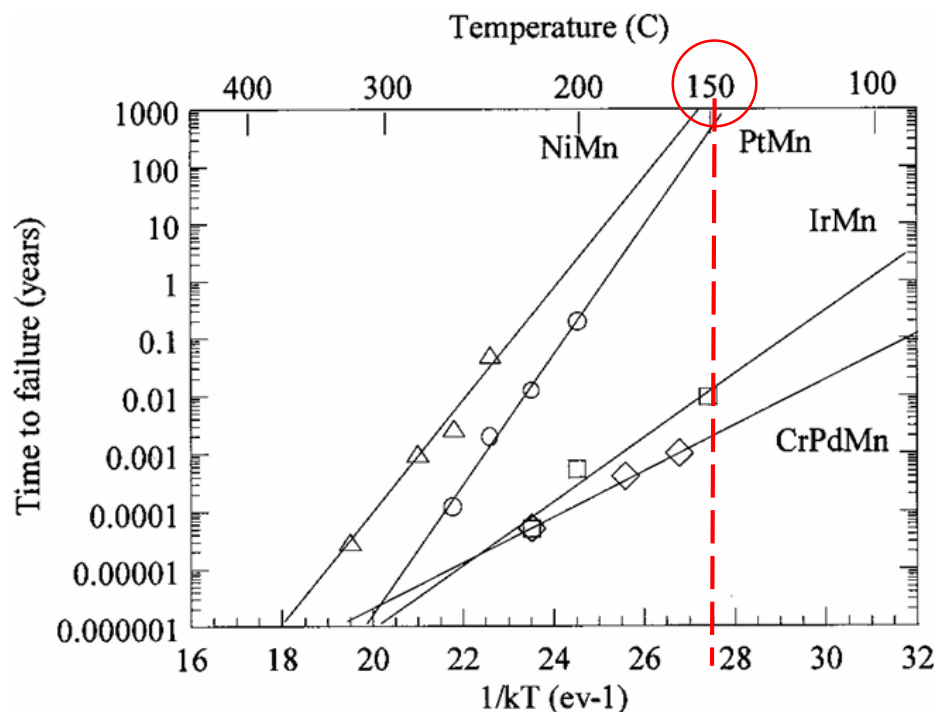
Selecting the AF material

High T_B



High thermal stability

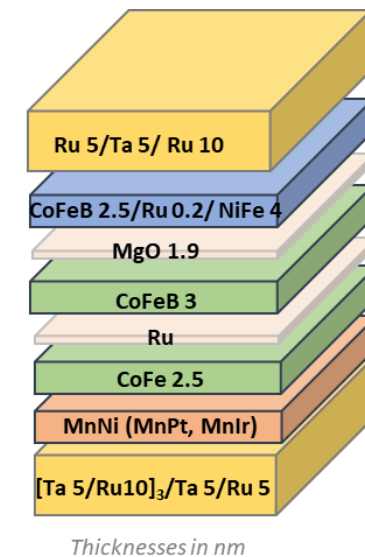
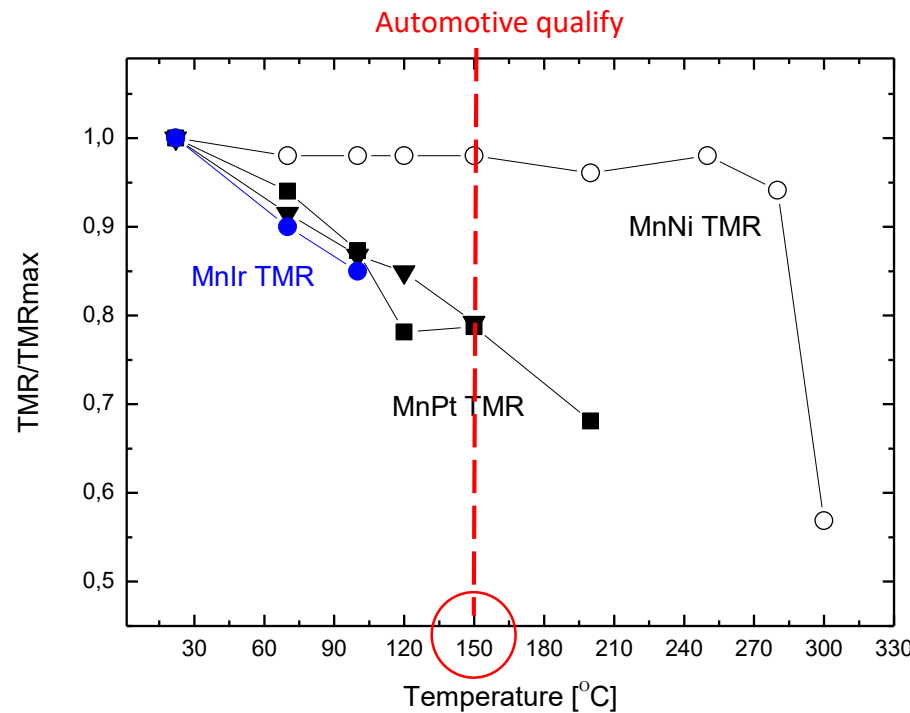
Nozieres et al.
J. Appl. Phys., 87 (8), 15 (2000)



Accelerated annealing tests

At 150°C →

1000 years - NiMn and PtMn
100 days - IrMn
20 h - CrPdMn



P.Araujo et. al.
(unpublished)

In summary:

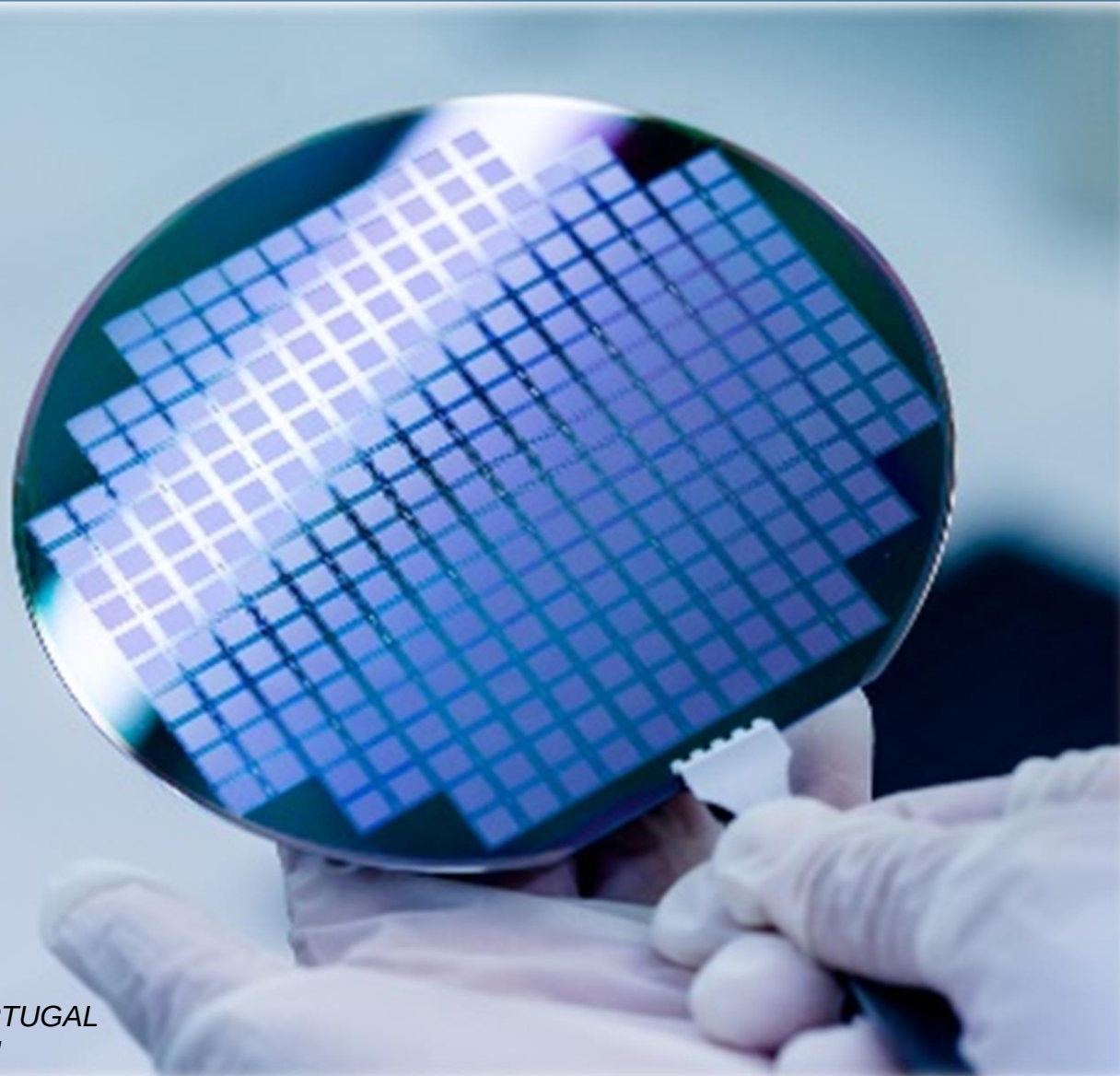
The perfect magnetoresistive sensor

- large output voltage: mV
- low field detection: pT
- tunable for large field detection: 80 mT
- low noise
- low hysteresis 0 mT
- linearity: < 1% non-linearity
- small footprint: 10 μm chip size
- low cost: < 0.20 €/chip
- high thermal stability: >120°C in harsh e.m environment
- compatible with CMOS modules
- compatible with large scale microfabrication
- compatible with flexible electronics

Is still to be found

Acknowledgments

INESC MN
Microsistemas &
Nanotecnologias



MADE IN PORTUGAL
By INESC-MN

